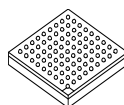
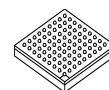




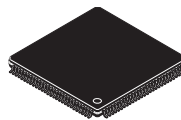
## MCF5373



MAPBGA-256  
17mm x 17mm



MAPBGA-196  
15mm x 15mm



QFP-160  
28mm x 28mm

# MCF537x ColdFire® Microprocessor Data Sheet

### Features

- Version 3 ColdFire variable-length RISC processor core
- System debug support
- JTAG support for system level board testing
- On-chip memories
  - 16-Kbyte unified write-back cache
  - 32-Kbyte dual-ported SRAM on CPU internal bus, accessible by core and non-core bus masters (e.g., DMA, FEC, and USB host and OTG)
- Power management
- Embedded Voice-over-IP (VoIP) system solution
- SDR/DDR SDRAM Controller
- Universal Serial Bus (USB) Host Controller
- Universal Serial Bus (USB) On-the-Go (OTG) controller
- Synchronous Serial Interface (SSI)
- Fast Ethernet Controller (FEC)
- Cryptography Hardware Accelerators
- FlexCAN Module
- Three Universal Asynchronous Receiver Transmitters (UARTs)
- I<sup>2</sup>C Module
- Queued Serial Peripheral Interface (QSPI)
- Pulse Width Modulation (PWM) module
- Real Time Clock
- Four 32-bit DMA Timers
- Software Watchdog Timer
- Four Periodic Interrupt Timers (PITs)
- Phase Locked Loop (PLL)
- Interrupt Controllers (x2)
- DMA Controller
- FlexBus (External Interface)
- Chip Configuration Module (CCM)
- Reset Controller
- General Purpose I/O interface

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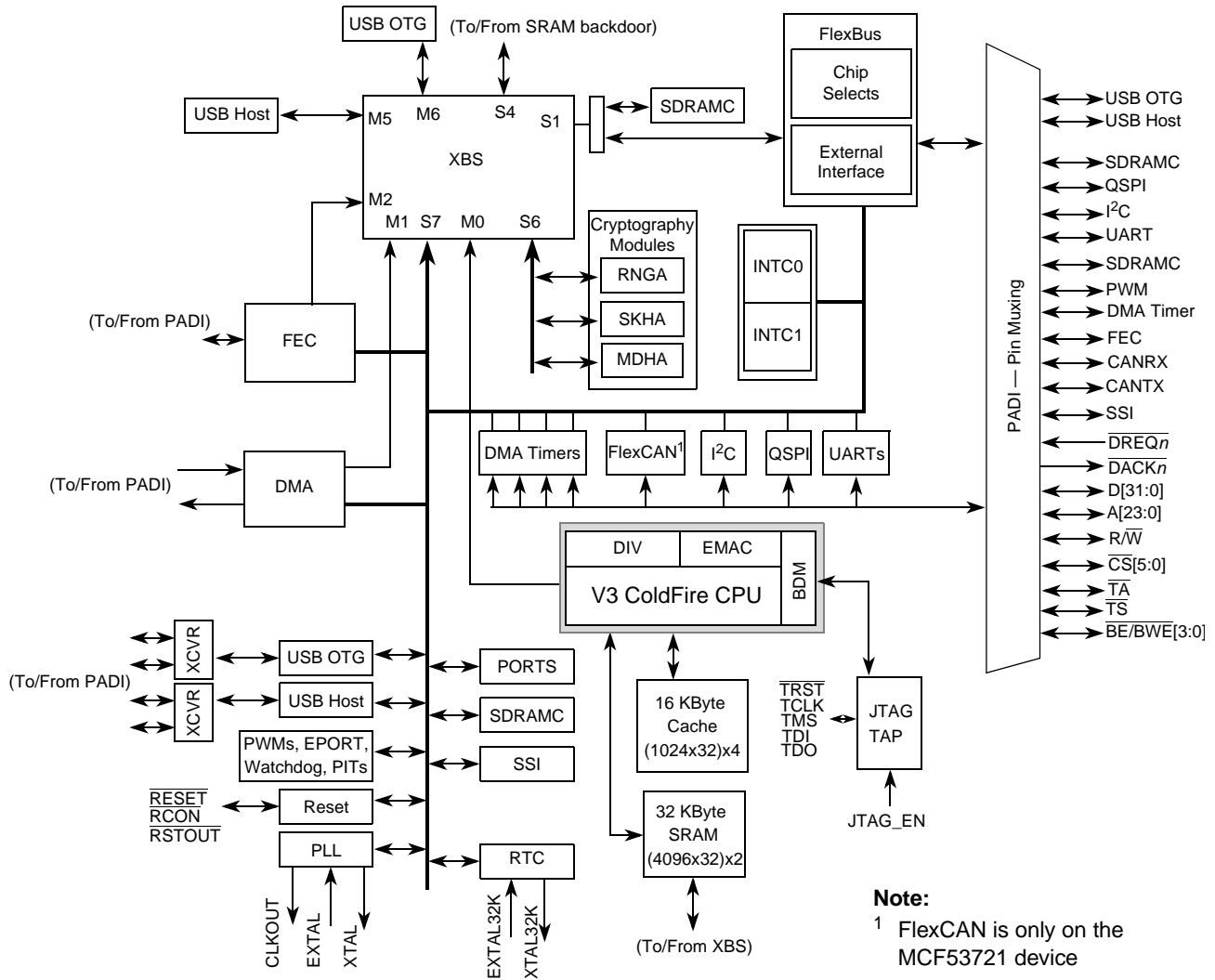


Figure 1. MCF5373 Block Diagram

# 1 MCF537x Family Comparison

The following table compares the various device derivatives available within the MCF537x family.

Table 1. MCF537x Family Configurations

| Module  | MCF5372       | MCF5372L      | MCF53721 | MCF5373       | MCF5373L      |
|---|---------------|---------------|----------|---------------|---------------|
| ColdFire Version 3 Core with EMAC (Enhanced Multiply-Accumulate Unit) | •             | •             | •        | •             | •             |
| Core (System) Clock   | up to 180 MHz | up to 240 MHz |          | up to 180 MHz | up to 240 MHz |
| Peripheral and External Bus Clock (Core clock ÷ 3)                    | up to 60 MHz  | up to 80 MHz  |          | up to 60 MHz  | up to 80 MHz  |
| Performance (Dhrystone/2.1 MIPS)                                      | up to 158     | up to 211     |          | up to 158     | up to 211     |
| Instruction/Data Cache  | 16 Kbytes     |               |          |               |               |

Because of an order from the United States International Trade Commission, BGA-packaged product lines and part numbers indicated here currently are not available from Freescale for import or sale in the United States prior to September 2010: MCF53721CVM240, MCF5372LCVM240, MCF5373LCVM240

**Table 1. MCF537x Family Configurations (continued)**

| Module   | MCF5372    | MCF5372L      | MCF53721      | MCF5373    | MCF5373L      |
|--|------------|---------------|---------------|------------|---------------|
| Static RAM (SRAM)                                | 32 Kbytes  |               |               |            |               |
| SDR/DDR SDRAM Controller                         | •          | •             | •             | •          | •             |
| USB 2.0 Host                                     | —          | •             | •             | —          | •             |
| USB 2.0 On-the-Go                                | —          | •             | •             | —          | •             |
| Synchronous Serial Interface (SSI)               | •          | •             | •             | •          | •             |
| Fast Ethernet Controller (FEC)                   | •          | •             | •             | •          | •             |
| Cryptography Hardware Accelerators               | —          | —             | —             | •          | •             |
| Embedded Voice-over-IP System Solution           | —          | —             | •             | —          | —             |
| FlexCAN 2.0B communication module                | —          | —             | •             | —          | —             |
| UARTs  | 3          | 3             | 3             | 3          | 3             |
| I <sup>2</sup> C                                 | •          | •             | •             | •          | •             |
| QSPI   | •          | •             | •             | •          | •             |
| PWM Module                                       | —          | •             | •             | —          | •             |
| Real Time Clock                                  | •          | •             | •             | •          | •             |
| 32-bit DMA Timers                                | 4          | 4             | 4             | 4          | 4             |
| Watchdog Timer (WDT)                             | •          | •             | •             | •          | •             |
| Periodic Interrupt Timers (PIT)                  | 4          | 4             | 4             | 4          | 4             |
| Edge Port Module (EPORT)                         | •          | •             | •             | •          | •             |
| Interrupt Controllers (INTC)                     | 2          | 2             | 2             | 2          | 2             |
| 16-channel Direct Memory Access (DMA)            | •          | •             | •             | •          | •             |
| FlexBus External Interface                       | •          | •             | •             | •          | •             |
| General Purpose I/O (GPIO)                       | up to 46   | up to 62      | up to 62      | up to 46   | up to 62      |
| JTAG - IEEE <sup>®</sup> 1149.1 Test Access Port | •          | •             | •             | •          | •             |
| Package  | 160<br>QFP | 196<br>MAPBGA | 196<br>MAPBGA | 160<br>QFP | 196<br>MAPBGA |

## 2 Ordering Information

**Table 2. Orderable Part Numbers**

| Freescall Part Number | Description                  | Package    | Speed   | Temperature    |
|-----------------------|------------------------------|------------|---------|----------------|
| MCF5372CAB180         | MCF5372 RISC Microprocessor  | 160 QFP    | 180 MHz | –40° to +85° C |
| MCF5372LCVM240        | MCF5372 RISC Microprocessor  | 196 MAPBGA | 240 MHz | –40° to +85° C |
| MCF53721CVM240        | MCF53721 RISC Microprocessor | 196 MAPBGA | 240 MHz | –40° to +85° C |
| MCF5373CAB180         | MCF5373 RISC Microprocessor  | 160 QFP    | 180 MHz | –40° to +85° C |
| MCF5373LCVM240        | MCF5373 RISC Microprocessor  | 196 MAPBGA | 240 MHz | –40° to +85° C |

## 3 Hardware Design Considerations

### 3.1 PLL Power Filtering

To further enhance noise isolation, an external filter is strongly recommended for PLL analog  $V_{DD}$  pins. The filter shown in Figure 2 should be connected between the board  $V_{DD}$  and the PLL $V_{DD}$  pins. The resistor and capacitors should be placed as close to the dedicated PLL $V_{DD}$  pin as possible.

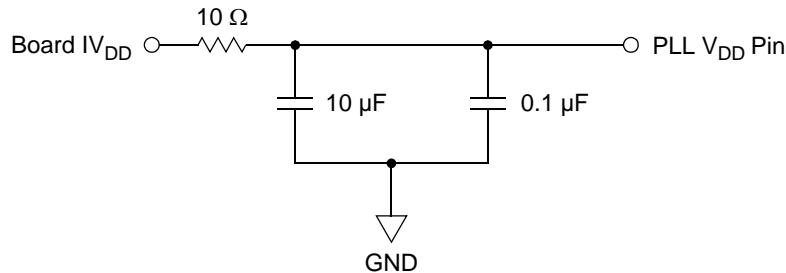


Figure 2. System PLL  $V_{DD}$  Power Filter

### 3.2 USB Power Filtering

To minimize noise, external filters are required for each of the USB power pins. The filter shown in Figure 3 should be connected between the board  $EV_{DD}$  or  $IV_{DD}$  and each of the USB $V_{DD}$  pins. The resistor and capacitors should be placed as close to the dedicated USB $V_{DD}$  pin as possible.

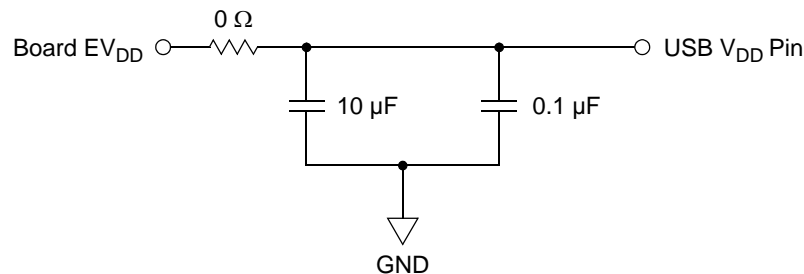


Figure 3. USB  $V_{DD}$  Power Filter

#### NOTE

In addition to the above filter circuitry, a 0.01 F capacitor is also recommended in parallel with those shown.

### 3.3 Supply Voltage Sequencing and Separation Cautions

The relationship between  $SDV_{DD}$  and  $EV_{DD}$  is non-critical during power-up and power-down sequences.  $SDV_{DD}$  (2.5V or 3.3V) and  $EV_{DD}$  are specified relative to  $IV_{DD}$ .

#### 3.3.1 Power Up Sequence

If  $EV_{DD}/SDV_{DD}$  are powered up with  $IV_{DD}$  at 0 V, the sense circuits in the I/O pads cause all pad output drivers connected to the  $EV_{DD}/SDV_{DD}$  to be in a high impedance state. There is no limit on how long after  $EV_{DD}/SDV_{DD}$  powers up before  $IV_{DD}$  must powered up.  $IV_{DD}$  should not lead the  $EV_{DD}$ ,  $SDV_{DD}$ , or PLL $V_{DD}$  by more than 0.4 V during power ramp-up or there is

high current in the internal ESD protection diodes. The rise times on the power supplies should be slower than 500 us to avoid turning on the internal ESD protection clamp diodes.

### 3.3.2 Power Down Sequence

If  $IV_{DD}/PLL_{V_{DD}}$  are powered down first, sense circuits in the I/O pads cause all output drivers to be in a high impedance state. There is no limit on how long after  $IV_{DD}$  and  $PLL_{V_{DD}}$  power down before  $EV_{DD}$  or  $SDV_{DD}$  must power down.  $IV_{DD}$  should not lag  $EV_{DD}$ ,  $SDV_{DD}$ , or  $PLL_{V_{DD}}$  going low by more than 0.4 V during power down or there is undesired high current in the ESD protection diodes. There are no requirements for the fall times of the power supplies.

The recommended power down sequence is as follows:

1. Drop  $IV_{DD}/PLL_{V_{DD}}$  to 0 V.
2. Drop  $EV_{DD}/SDV_{DD}$  supplies.

## 4 Pin Assignments and Reset States

### 4.1 Signal Multiplexing

The following table lists all the MCF537x pins grouped by function. The Dir column is the direction for the primary function of the pin only. Refer to Section 7, “Package Information,” for package diagrams. For a more detailed discussion of the MCF537x signals, consult the *MCF5373 Reference Manual* (MCF5373RM).

#### NOTE

In this table and throughout this document, a single signal within a group is designated without square brackets (i.e., A23), while designations for multiple signals within a group use brackets (i.e., A[23:21]) and is meant to include all signals within the two bracketed numbers when these numbers are separated by a colon.

#### NOTE

The primary functionality of a pin is not necessarily its default functionality. Pins that are muxed with GPIO default to their GPIO functionality.

**Table 3. MCF5372/3 Signal Information and Muxing**

| Signal Name                 | GPIO | Alternate 1 | Alternate 2 | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA |
|-----------------------------|------|-------------|-------------|-------------------|----------------|-------------------------------|--|
| <b>Reset</b>                |      |             |             |                   |                |                               |  |
| $\overline{\text{RESET}}^2$ | —    | —           | —           | I                 | EVDD           | 95                            | K13  |
| $\overline{\text{RSTOUT}}$  | —    | —           | —           | O                 | EVDD           | 86                            | L12  |
| <b>Clock</b>                |      |             |             |                   |                |                               |  |
| EXTAL                       | —    | —           | —           | I                 | EVDD           | 91                            | L14  |
| XTAL <sup>2</sup>           | —    | —           | —           | O                 | EVDD           | 93                            | K14  |
| EXTAL32K                    | —    | —           | —           | I                 | EVDD           | —                             | P13  |
| XTAL32K                     | —    | —           | —           | O                 | EVDD           | —                             | N13  |
| FB_CLK                      | —    | —           | —           | O                 | SDVDD          | 40                            | N1   |

Table 3. MCF5372/3 Signal Information and Muxing (continued)

| Signal Name              | GPIO     | Alternate 1                 | Alternate 2 | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA                 |
|--------------------------|----------|-----------------------------|-------------|-------------------|----------------|-------------------------------|--|
| <b>Mode Selection</b>    |          |                             |             |                   |                |                               |  |
| $\overline{RCON}^2$      | —        | —                           | —           | I                 | EVDD           | 72                            | P8   |
| DRAMSEL                  | —        | —                           | —           | I                 | EVDD           | 92                            | J11  |
| <b>FlexBus</b>           |          |                             |             |                   |                |                               |  |
| A[23:22]                 | —        | $\overline{FB\_CS}[5:4]$    | —           | O                 | SDVDD          | 134, 133                      | A9, B9   |
| A[21:16]                 | —        | —                           | —           | O                 | SDVDD          | 132–127                       | C9, D9, A10,<br>B10, C10, D10                                  |
| A[15:14]                 | —        | SD_BA[1:0] <sup>3</sup>     | —           | O                 | SDVDD          | 126, 123                      | A11, B11   |
| A[13:11]                 | —        | SD_A[13:11] <sup>3</sup>    | —           | O                 | SDVDD          | 120–118                       | C11, A12, B12  |
| A10                      | —        | —                           | —           | O                 | SDVDD          | 11 7                          | A13  |
| A[9:0]                   | —        | SD_A[9:0] <sup>3</sup>      | —           | O                 | SDVDD          | 116–107                       | A14, B14, B13,<br>C12, D11, C14,<br>C13, D14–D12               |
| D[31:16]                 | —        | SD_D[31:16] <sup>4</sup>    | —           | I/O               | SDVDD          | 27–34, 46–53                  | J2, J1, K4–K1,<br>L4, L3, N2, P1,<br>P2, N3, L5, P3,<br>N4, P4 |
| D[15:1]                  | —        | FB_D[31:17] <sup>4</sup>    | —           | I/O               | SDVDD          | 16–23, 57–63                  | F2, F1, G4–G1,<br>H4, H3, L6, M6,<br>N6, P6, L7, M7,<br>N7     |
| D0 <sup>2</sup>          | —        | FB_D[16] <sup>4</sup>       | —           | I/O               | SDVDD          | 64                            | P7   |
| $\overline{BE/BWE}[3:0]$ | PBE[3:0] | $\overline{SD\_DQM}[3:0]^3$ | —           | O                 | SDVDD          | 26, 54, 24, 56                | J3, M5, H2, P5   |
| $\overline{OE}$          | PBUSCTL3 | —                           | —           | O                 | SDVDD          | 66                            | M8   |
| $\overline{TA}^2$        | PBUSCTL2 | —                           | —           | I                 | SDVDD          | 106                           | E14  |
| R/W                      | PBUSCTL1 | —                           | —           | O                 | SDVDD          | 65                            | L8   |
| $\overline{TS}$          | PBUSCTL0 | $\overline{DACK0}$          | —           | O                 | SDVDD          | 12                            | E2   |
| <b>Chip Selects</b>      |          |                             |             |                   |                |                               |  |
| $\overline{FB\_CS}[5:4]$ | PCS[5:4] | —                           | —           | O                 | SDVDD          | —                             | D8, C8   |
| $\overline{FB\_CS}[3:2]$ | PCS[3:2] | —                           | —           | O                 | SDVDD          | —                             | B8, A8   |
| $\overline{FB\_CS}1$     | PCS1     | —                           | —           | O                 | SDVDD          | 135                           | D7   |
| $\overline{FB\_CS}0$     | —        | —                           | —           | O                 | SDVDD          | 136                           | C7   |
| <b>SDRAM Controller</b>  |          |                             |             |                   |                |                               |  |
| SD_A10                   | —        | —                           | —           | O                 | SDVDD          | 43                            | M2   |
| SD_CKE                   | —        | —                           | —           | O                 | SDVDD          | 14                            | F4   |

Table 3. MCF5372/3 Signal Information and Muxing (continued)

| Signal Name                                 | GPIO               | Alternate 1                 | Alternate 2 | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA |
|---|--------------------|-----------------------------|-------------|-------------------|----------------|-------------------------------|--|
| SD_CLK                                      | —                  | —                           | —           | O                 | SDVDD          | 37                            | L1   |
| $\overline{\text{SD\_CLK}}$                 | —                  | —                           | —           | O                 | SDVDD          | 38                            | M1   |
| $\overline{\text{SD\_CS0}}$                 | —                  | —                           | —           | O                 | SDVDD          | 15                            | F3   |
| SD_DQS3                                     | —                  | —                           | —           | O                 | SDVDD          | 25                            | H1   |
| SD_DQS2                                     | —                  | —                           | —           | O                 | SDVDD          | 55                            | N5   |
| $\overline{\text{SD\_SCAS}}$                | —                  | —                           | —           | O                 | SDVDD          | 44                            | M3   |
| $\overline{\text{SD\_SRAS}}$                | —                  | —                           | —           | O                 | SDVDD          | 45                            | M4   |
| SD_SDR_DQS                                  | —                  | —                           | —           | O                 | SDVDD          | 35                            | L2   |
| $\overline{\text{SD\_WE}}$                  | —                  | —                           | —           | O                 | SDVDD          | 13                            | E1   |
| <b>External Interrupts Port<sup>5</sup></b> |                    |                             |             |                   |                |                               |  |
| $\overline{\text{IRQ7}}^2$                  | PIRQ7 <sup>2</sup> | —                           | —           | I                 | EVDD           | 102                           | F13  |
| $\overline{\text{IRQ6}}^2$                  | PIRQ6 <sup>2</sup> | USBHOST_<br>VBUS_EN         | —           | I                 | EVDD           | —                             | F12  |
| $\overline{\text{IRQ5}}^2$                  | PIRQ5 <sup>2</sup> | USBHOST_<br>VBUS_OC         | —           | I                 | EVDD           | —                             | F11  |
| $\overline{\text{IRQ4}}^2$                  | PIRQ4 <sup>2</sup> | SSI_MCLK                    | —           | I                 | EVDD           | 101                           | G14  |
| $\overline{\text{IRQ3}}^2$                  | PIRQ3 <sup>2</sup> | —                           | —           | I                 | EVDD           | —                             | G13  |
| $\overline{\text{IRQ2}}^2$                  | PIRQ2 <sup>2</sup> | USB_CLKIN                   | —           | I                 | EVDD           | —                             | G12  |
| $\overline{\text{IRQ1}}^2$                  | PIRQ1 <sup>2</sup> | $\overline{\text{DREQ1}}^2$ | SSI_CLKIN   | I                 | EVDD           | 100                           | G11  |
| <b>FEC</b>                                  |                    |                             |             |                   |                |                               |  |
| FEC_MDC                                     | PFECI2C3           | I2C_SCL <sup>2</sup>        | —           | O                 | EVDD           | 4                             | B1   |
| FEC_MDIO                                    | PFECI2C2           | I2C_SDA <sup>2</sup>        | —           | I/O               | EVDD           | 3                             | A1   |
| FEC_COL                                     | PFECH7             | —                           | —           | I                 | EVDD           | 144                           | B6   |
| FEC_CRIS                                    | PFECH6             | —                           | —           | I                 | EVDD           | 145                           | A6   |
| FEC_RXCLK                                   | PFECH5             | —                           | —           | I                 | EVDD           | 146                           | A5   |
| FEC_RXDV                                    | PFECH4             | —                           | —           | I                 | EVDD           | 147                           | B5   |
| FEC_RXD[3:0]                                | PFECH[3:0]         | —                           | —           | I                 | EVDD           | 148–151                       | C5, D5, A4, B4                                 |
| FEC_RXER                                    | PFECL7             | —                           | —           | I                 | EVDD           | 152                           | C4   |
| FEC_TXCLK                                   | PFECL6             | —                           | —           | I                 | EVDD           | 153                           | A3   |
| FEC_TXEN                                    | PFECL5             | —                           | —           | O                 | EVDD           | 154                           | B3   |
| FEC_TXER                                    | PFECL4             | —                           | —           | O                 | EVDD           | 155                           | A2   |
| FEC_TXD[3:0]                                | PFECL[3:0]         | —                           | —           | O                 | EVDD           | 157, 158, 1, 2                | D4, C3, B2, C2                                 |



Table 3. MCF5372/3 Signal Information and Muxing (continued)

| Signal Name  | GPIO     | Alternate 1          | Alternate 2  | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA |
|--|----------|----------------------|--------------|-------------------|----------------|-------------------------------|--|
| <b>USB Host &amp; USB On-the-Go</b>  |          |                      |              |                   |                |                               |  |
| USBOTG_M   | —        | —                    | —            | I/O               | USB VDD        | —                             | H14  |
| USBOTG_P   | —        | —                    | —            | I/O               | USB VDD        | —                             | H13  |
| USBHOST_M  | —        | —                    | —            | I/O               | USB VDD        | —                             | J13  |
| USBHOST_P  | —        | —                    | —            | I/O               | USB VDD        | —                             | J12  |
| <b>FlexCAN (MCF53721 only)</b>   |          |                      |              |                   |                |                               |  |
| CANRX and CANTX do not have dedicated bond pads. Please refer to the following pins for muxing:<br>I2C_SDA for CANRX and I2C_SCL for CANTX.  |          |                      |              |                   |                |                               |  |
| <b>PWM</b>   |          |                      |              |                   |                |                               |  |
| PWM7   | PPWM7    | —                    | —            | I/O               | EVDD           | —                             | E13  |
| PWM5   | PPWM5    | —                    | —            | I/O               | EVDD           | —                             | E12  |
| PWM3   | PPWM3    | DT3OUT               | DT3IN        | I/O               | EVDD           | —                             | E11  |
| PWM1   | PPWM1    | DT2OUT               | DT2IN        | I/O               | EVDD           | —                             | F14  |
| <b>SSI</b>   |          |                      |              |                   |                |                               |  |
| The SSI signals do not have dedicated bond pads. Please refer to the following pins for muxing: $\overline{IRQ4}$ for SSI_MCLK, $\overline{IRQ1}$ for SSI_CLKIN, $\overline{U1CTS}$ for SSI_BCLK, $\overline{U1RTS}$ for SSI_FS, U1RXD for SSI_RXD, and U1TXD for SSI_TXD                  |          |                      |              |                   |                |                               |  |
| <b>I<sup>2</sup>C</b>  |          |                      |              |                   |                |                               |  |
| I2C_SCL <sup>2</sup>   | PFECI2C1 | CANTX <sup>6</sup>   | U2TXD        | I/O               | EVDD           | —                             | E3   |
| I2C_SDA <sup>2</sup>   | PFECI2C0 | CANRX <sup>6</sup>   | U2RXD        | I/O               | EVDD           | —                             | E4   |
| <b>DMA</b>   |          |                      |              |                   |                |                               |  |
| $\overline{DACK[1:0]}$ and $\overline{DREQ[1:0]}$ do not have dedicated bond pads. Please refer to the following pins for muxing:<br>$\overline{TS}$ for $\overline{DACK0}$ , DT0IN for $\overline{DREQ0}$ , DT1IN for $\overline{DACK1}$ , and $\overline{IRQ1}$ for $\overline{DREQ1}$ . |          |                      |              |                   |                |                               |  |
| <b>QSPI</b>  |          |                      |              |                   |                |                               |  |
| QSPI_CS2   | PQSPI5   | $\overline{U2RTS}$   | —            | O                 | EVDD           | 78                            | N12  |
| QSPI_CS1   | PQSPI4   | PWM7                 | USBOTG_PU_EN | O                 | EVDD           | —                             | M12  |
| QSPI_CS0   | PQSPI3   | PWM5                 | —            | O                 | EVDD           | —                             | M11  |
| QSPI_CLK   | PQSPI2   | I2C_SCL <sup>2</sup> | —            | O                 | EVDD           | 77                            | P12  |
| QSPI_DIN   | PQSPI1   | $\overline{U2CTS}$   | —            | I                 | EVDD           | 75                            | P11  |
| QSPI_DOUT  | PQSPI0   | I2C_SDA <sup>2</sup> | —            | O                 | EVDD           | 76                            | N11  |

Table 3. MCF5372/3 Signal Information and Muxing (continued)

| Signal Name   | GPIO    | Alternate 1          | Alternate 2          | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA |
|---|---------|----------------------|----------------------|-------------------|----------------|-------------------------------|--|
| <b>UARTs</b>  |         |                      |                      |                   |                |                               |  |
| $\overline{U1CTS}$  | PUARTL7 | SSI_BCLK             | —                    | I                 | EVDD           | 143                           | C6   |
| $\overline{U1RTS}$  | PUARTL6 | SSI_FS               | —                    | O                 | EVDD           | 142                           | D6   |
| U1TXD   | PUARTL5 | SSI_TXD <sup>2</sup> | —                    | O                 | EVDD           | 141                           | A7   |
| U1RXD   | PUARTL4 | SSI_RXD <sup>2</sup> | —                    | I                 | EVDD           | 140                           | B7   |
| $\overline{U0CTS}$  | PUARTL3 | —                    | —                    | I                 | EVDD           | 85                            | M14  |
| $\overline{U0RTS}$  | PUARTL2 | —                    | —                    | O                 | EVDD           | 84                            | M13  |
| U0TXD   | PUARTL1 | —                    | —                    | O                 | EVDD           | 83                            | N14  |
| U0RXD   | PUARTL0 | —                    | —                    | I                 | EVDD           | 80                            | P14  |
| <b>Note:</b> The UART2 signals are multiplexed on the QSPI, DMA Timers, and I2C pins. |         |                      |                      |                   |                |                               |  |
| <b>DMA Timers</b>   |         |                      |                      |                   |                |                               |  |
| DT3IN   | PTIMER3 | DT3OUT               | U2RXD                | I                 | EVDD           | 8                             | D1   |
| DT2IN   | PTIMER2 | DT2OUT               | U2TXD                | I                 | EVDD           | 7                             | C1   |
| DT1IN   | PTIMER1 | DT1OUT               | $\overline{DACK1}$   | I                 | EVDD           | 6                             | D2   |
| DT0IN   | PTIMER0 | DT0OUT               | $\overline{DREQ0}^2$ | I                 | EVDD           | 5                             | D3   |
| <b>BDM/JTAG<sup>7</sup></b>   |         |                      |                      |                   |                |                               |  |
| JTAG_EN <sup>8</sup>  | —       | —                    | —                    | I                 | EVDD           | 96                            | G10  |
| DSCLK   | —       | $\overline{TRST}^2$  | —                    | I                 | EVDD           | 88                            | K11  |
| PSTCLK  | —       | TCLK <sup>2</sup>    | —                    | O                 | EVDD           | 70                            | N8   |
| $\overline{BKPT}$   | —       | TMS <sup>2</sup>     | —                    | I                 | EVDD           | 87                            | L13  |
| DSI   | —       | TDI <sup>2</sup>     | —                    | I                 | EVDD           | 90                            | K12  |
| DSO   | —       | TDO                  | —                    | O                 | EVDD           | 74                            | L11  |
| DDATA[3:0]  | —       | —                    | —                    | O                 | EVDD           | —                             | L9, M9, N9, P9                                 |
| PST[3:0]  | —       | —                    | —                    | O                 | EVDD           | —                             | L10, M10, N10, P10                             |
| ALLPST  | —       | —                    | —                    | O                 | EVDD           | 73                            | —  |

Table 3. MCF5372/3 Signal Information and Muxing (continued)

| Signal Name           | GPIO | Alternate 1 | Alternate 2 | Dir. <sup>1</sup> | Voltage Domain | MCF5372<br>MCF5373<br>160 QFP                | MCF5372L<br>MCF53721<br>MCF5373L<br>196 MAPBGA |
|-----------------------|------|-------------|-------------|-------------------|----------------|--|--|
| <b>Test</b>           |      |             |             |                   |                |  |  |
| TEST <sup>8</sup>     | —    | —           | —           | I                 | EVDD           | 124  | E10  |
| <b>Power Supplies</b> |      |             |             |                   |                |  |  |
| EVDD                  | —    | —           | —           | —                 | —              | 9, 69, 71, 81, 94,<br>103, 139, 160          | E6, E7, F5–F7,<br>G5, H10, J8,<br>K8–K9        |
| IVDD                  | —    | —           | —           | —                 | —              | 36, 79, 97, 125,<br>156                      | E5, J9, K5, K10                                |
| PLL_VDD               | —    | —           | —           | —                 | —              | 99   | J10  |
| SD_VDD                | —    | —           | —           | —                 | —              | 11, 39, 41, 67,<br>105, 121, 137             | E8–E9, F8–F10,<br>J4–J7, H5, K6,<br>K7         |
| USB_VDD               | —    | —           | —           | —                 | —              | —  | H12  |
| VSS                   | —    | —           | —           | —                 | —              | 10, 42, 68, 82,<br>89, 104, 122,<br>138, 159 | G6–G9, H6–H9                                   |
| PLL_VSS               | —    | —           | —           | —                 | —              | 98   | H11  |
| USB_VSS               | —    | —           | —           | —                 | —              | —  | J14  |

<sup>1</sup> Refers to pin's primary function.

<sup>2</sup> Pull-up enabled internally on this signal for this mode.

<sup>3</sup> The SDRAM functions of these signals are not programmable by the user. They are dynamically switched by the processor when accessing SDRAM memory space and are included here for completeness.

<sup>4</sup> Primary functionality selected by asserting the DRAMSEL signal (SDR mode). Alternate functionality selected by negating the DRAMSEL signal (DDR mode). The GPIO module is not responsible for assigning these pins.

<sup>5</sup> GPIO functionality is determined by the edge port module. The GPIO module is only responsible for assigning the alternate functions.

<sup>6</sup> MCF53721 only.

<sup>7</sup> If JTAG\_EN is asserted, these pins default to Alternate 1 (JTAG) functionality. The GPIO module is not responsible for assigning these pins.

<sup>8</sup> Pull-down enabled internally on this signal for this mode.

## NOTE

## 4.2 Pinout—196 MAPBGA

The pinout for the MCF5373LCVM240, MCF5372LCVM240, and MCF53721CVM240 packages are shown below.

|   | 1                           | 2                           | 3                           | 4                           | 5                           | 6                         | 7                           | 8                           | 9      | 10      | 11                             | 12                         | 13                        | 14                        |   |
|---|-----------------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|---------------------------|-----------------------------|-----------------------------|--------|---------|--------------------------------|----------------------------|---------------------------|---------------------------|---|
| A | FEC_MDIO                    | FEC_TXER                    | FEC_TXCLK                   | FEC_RXD1                    | FEC_RXCLK                   | FEC_CRS                   | U1TXD                       | $\overline{\text{FB\_CS2}}$ | A23    | A19     | A15                            | A12                        | A10                       | A9                        | A |
| B | FEC_MDC                     | FEC_TXD1                    | FEC_TXEN                    | FEC_RXD0                    | FEC_RXDV                    | FEC_COL                   | U1RXD                       | $\overline{\text{FB\_CS3}}$ | A22/   | A18     | A14                            | A11                        | A7                        | A8                        | B |
| C | DT2IN                       | FEC_TXD0                    | FEC_TXD2                    | FEC_RXER                    | FEC_RXD3                    | $\overline{\text{U1CTS}}$ | $\overline{\text{FB\_CS0}}$ | $\overline{\text{FB\_CS4}}$ | A21    | A17     | A13                            | A6                         | A3                        | A4                        | C |
| D | DT3IN                       | DT1IN                       | DT0IN                       | FEC_TXD3                    | FEC_RXD2                    | $\overline{\text{U1RTS}}$ | $\overline{\text{FB\_CS1}}$ | $\overline{\text{FB\_CS5}}$ | A20    | A16     | A5                             | A0                         | A1                        | A2                        | D |
| E | $\overline{\text{SD\_WE}}$  | $\overline{\text{TS}}$      | I2C_SCL                     | I2C_SDA                     | IVDD                        | EVDD                      | EVDD                        | SD_VDD                      | SD_VDD | TEST    | PWM3                           | PWM5                       | PWM7                      | $\overline{\text{TA}}$    | E |
| F | D14                         | D15                         | $\overline{\text{SD\_CS0}}$ | SD_CKE                      | EVDD                        | EVDD                      | EVDD                        | SD_VDD                      | SD_VDD | SD_VDD  | $\overline{\text{IRQ5}}$       | $\overline{\text{IRQ6}}$   | $\overline{\text{IRQ7}}$  | PWM1                      | F |
| G | D10                         | D11                         | D12                         | D13                         | EVDD                        | VSS                       | VSS                         | VSS                         | VSS    | JTAG_EN | $\overline{\text{IRQ1}}$       | $\overline{\text{IRQ2}}$   | $\overline{\text{IRQ3}}$  | $\overline{\text{IRQ4}}$  | G |
| H | SD_DQS3                     | $\overline{\text{BE/BWE1}}$ | D8                          | D9                          | SD_VDD                      | VSS                       | VSS                         | VSS                         | VSS    | EVDD    | PLL_VSS                        | USBOTG_VDD                 | USB_OTG_P                 | USB_OTG_M                 | H |
| J | D30                         | D31                         | $\overline{\text{BE/BWE3}}$ | SD_VDD                      | SD_VDD                      | SD_VDD                    | SD_VDD                      | EVDD                        | IVDD   | PLL_VDD | DRAM_SEL                       | USB_HOST_P                 | USB_HOST_M                | USBHOST_VSS               | J |
| K | D26                         | D27                         | D28                         | D29                         | IVDD                        | SD_VDD                    | SD_VDD                      | EVDD                        | EVDD   | IVDD    | $\overline{\text{TRST/DSCLK}}$ | TDI/DSI                    | $\overline{\text{RESET}}$ | XTAL                      | K |
| L | SD_CLK                      | SD_DR_DQS                   | D24                         | D25                         | D19                         | D7                        | D3                          | R/W                         | DDATA3 | PST3    | TDO/DSO                        | $\overline{\text{RSTOUT}}$ | TMS/BKPT                  | EXTAL                     | L |
| M | $\overline{\text{SD\_CLK}}$ | SD_A10                      | $\overline{\text{SD\_CAS}}$ | $\overline{\text{SD\_RAS}}$ | $\overline{\text{BE/BWE2}}$ | D6                        | D2                          | $\overline{\text{OE}}$      | DDATA2 | PST2    | QSPI_CS0                       | QSPI_CS1                   | $\overline{\text{U0RTS}}$ | $\overline{\text{U0CTS}}$ | M |
| N | FB_CLK                      | D23                         | D20                         | D17                         | SD_DQS2                     | D5                        | D1                          | TCLK/PSTCLK                 | DDATA1 | PST1    | QSPI_DOUT                      | QSPI_CS2                   | XTAL 32K                  | U0TXD                     | N |
| P | D22                         | D21                         | D18                         | D16                         | $\overline{\text{BE/BWE0}}$ | D4                        | D0                          | $\overline{\text{RCON}}$    | DDATA0 | PST0    | QSPI_DIN                       | QSPI_CLK                   | EXTAL 32K                 | U0RXD                     | P |
|   | 1                           | 2                           | 3                           | 4                           | 5                           | 6                         | 7                           | 8                           | 9      | 10      | 11                             | 12                         | 13                        | 14                        |   |

Figure 4. MCF5373LCVM240, MCF5372LCVM240, and MCF53721CVM240 Pinout Top View (196 MAPBGA)

Because of an order from the United States International Trade Commission, BGA-packaged product lines and part numbers indicated here currently are not available from Freescale for import or sale in the United States prior to September 2010: MCF53721CVM240, MCF5372LCVM240, MCF5373LCVM240

### 4.3 Pinout—160 QFP

The pinout for the MCF5372CAB180 and MCF5373CAB180 packages is shown below.

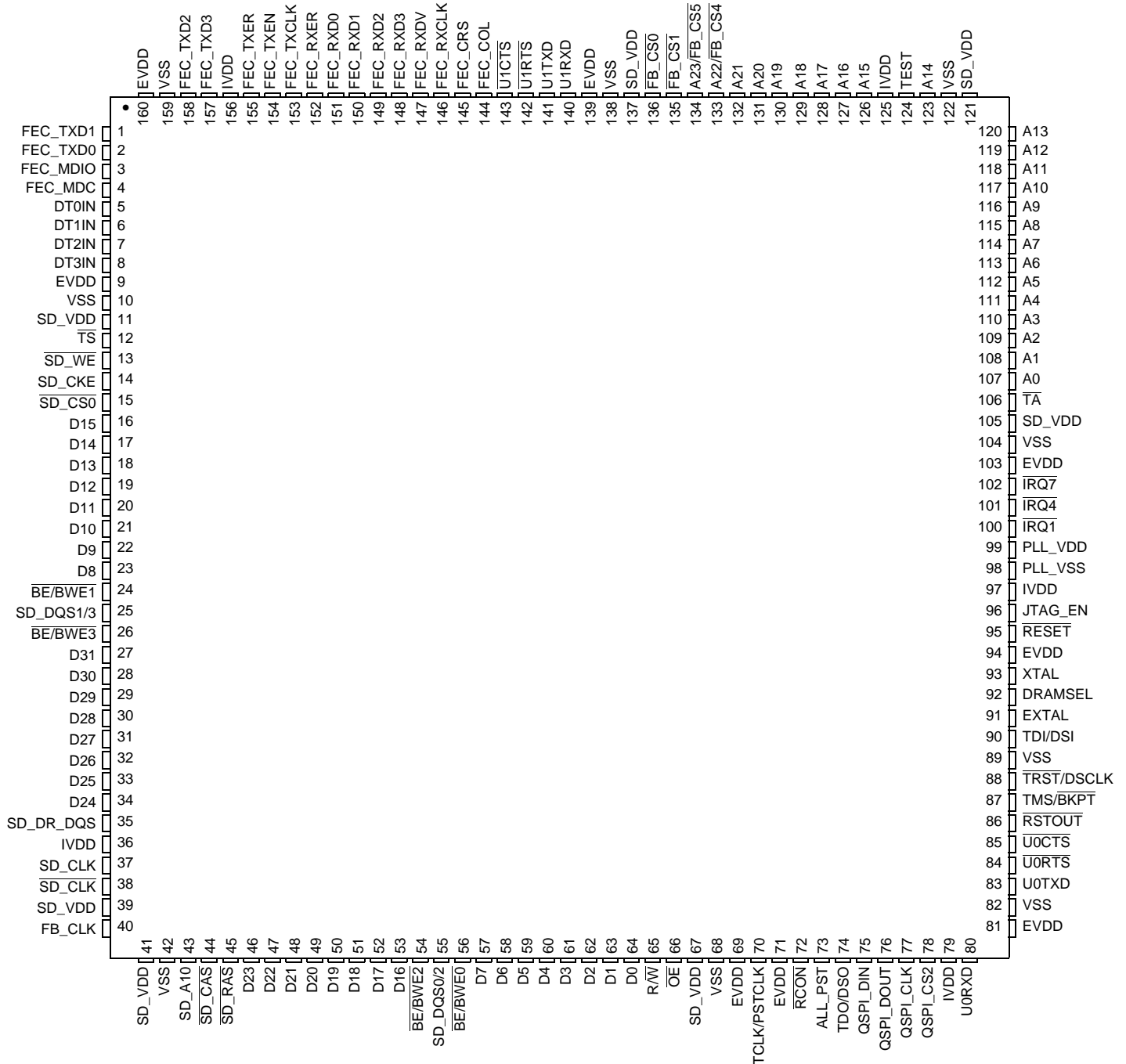


Figure 5. MCF5372CAB180 and MCF5373CAB180 Pinout Top View (160 QFP)

## 5 Electrical Characteristics

This document contains electrical specification tables and reference timing diagrams for the MCF5373 microcontroller unit. This section contains detailed information on power considerations, DC/AC electrical characteristics, and AC timing specifications of MCF5373.

The electrical specifications are preliminary and are from previous designs or design simulations. These specifications may not be fully tested or guaranteed at this early stage of the product life cycle. However, for production silicon, these specifications will be met. Finalized specifications will be published after complete characterization and device qualifications have been completed.

### NOTE

The parameters specified in this MCU document supersede any values found in the module specifications.

### 5.1 Maximum Ratings

Table 4. Absolute Maximum Ratings<sup>1, 2</sup>

| Rating   | Symbol                   | Value         | Unit |
|--|--------------------------|---------------|------|
| Core Supply Voltage  | $IV_{DD}$                | - 0.5 to +2.0 | V    |
| CMOS Pad Supply Voltage  | $EV_{DD}$                | - 0.3 to +4.0 | V    |
| DDR/Memory Pad Supply Voltage  | $SDV_{DD}$               | - 0.3 to +4.0 | V    |
| PLL Supply Voltage   | $PLL_{V_{DD}}$           | - 0.3 to +2.0 | V    |
| Digital Input Voltage <sup>3</sup>   | $V_{IN}$                 | - 0.3 to +3.6 | V    |
| Instantaneous Maximum Current<br>Single pin limit (applies to all pins) <sup>3, 4, 5</sup> | $I_D$                    | 25            | mA   |
| Operating Temperature Range (Packaged)   | $T_A$<br>( $T_L - T_H$ ) | - 40 to +85   | °C   |
| Storage Temperature Range  | $T_{stg}$                | - 55 to +150  | °C   |

<sup>1</sup> Functional operating conditions are given in [Section 5.4, "DC Electrical Specifications."](#) Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Continued operation at these levels may affect device reliability or cause permanent damage to the device.

<sup>2</sup> This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level ( $V_{SS}$  or  $EV_{DD}$ ).

<sup>3</sup> Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, and then use the larger of the two values.

<sup>4</sup> All functional non-supply pins are internally clamped to  $V_{SS}$  and  $EV_{DD}$ .

<sup>5</sup> Power supply must maintain regulation within operating  $EV_{DD}$  range during instantaneous and operating maximum current conditions. If positive injection current ( $V_{in} > EV_{DD}$ ) is greater than  $I_D$ , the injection current may flow out of  $EV_{DD}$  and could result in external power supply going out of regulation. Ensure external  $EV_{DD}$  load shunts current greater than maximum injection current. This is the greatest risk when the MCU is not consuming power (ex; no clock). Power supply must maintain regulation within operating  $EV_{DD}$  range during instantaneous and operating maximum current conditions.

## 5.2 Thermal Characteristics

Table 5. Thermal Characteristics

| Characteristic                          |                         | Symbol         | 256MBGA           | 196MBGA           | 160QFP            | Unit |
|---|-------------------------|----------------|-------------------|-------------------|-------------------|------|
| Junction to ambient, natural convection | Four layer board (2s2p) | $\theta_{JMA}$ | 37 <sup>1,2</sup> | 42 <sup>1,2</sup> | 49 <sup>1,2</sup> | °C/W |
| Junction to ambient (@200 ft/min)       | Four layer board (2s2p) | $\theta_{JMA}$ | 34 <sup>1,2</sup> | 38 <sup>1,2</sup> | 44 <sup>1,2</sup> | °C/W |
| Junction to board                       |                         | $\theta_{JB}$  | 27 <sup>3</sup>   | 32 <sup>3</sup>   | 40 <sup>3</sup>   | °C/W |
| Junction to case                        |                         | $\theta_{JC}$  | 16 <sup>4</sup>   | 19 <sup>4</sup>   | 39 <sup>4</sup>   | °C/W |
| Junction to top of package              |                         | $\Psi_{jt}$    | 4 <sup>1,5</sup>  | 5 <sup>1,5</sup>  | 12 <sup>1,5</sup> | °C/W |
| Maximum operating junction temperature  |                         | $T_j$          | 105               | 105               | 105               | °C   |

<sup>1</sup>  $\theta_{JMA}$  and  $\Psi_{jt}$  parameters are simulated in conformance with EIA/JESD Standard 51-2 for natural convection. Freescale recommends the use of  $\theta_{JMA}$  and power dissipation specifications in the system design to prevent device junction temperatures from exceeding the rated specification. System designers should be aware that device junction temperatures can be significantly influenced by board layout and surrounding devices. Conformance to the device junction temperature specification can be verified by physical measurement in the customer's system using the  $\Psi_{jt}$  parameter, the device power dissipation, and the method described in EIA/JESD Standard 51-2.

<sup>2</sup> Per JEDEC JESD51-6 with the board horizontal.

<sup>3</sup> Thermal resistance between the die and the printed circuit board in conformance with JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.

<sup>4</sup> Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).

<sup>5</sup> Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written in conformance with Psi-JT.

The average chip-junction temperature ( $T_j$ ) in °C can be obtained from:

$$T_j = T_A + (P_D \times \theta_{JMA}) \quad \text{Eqn. 1}$$

Where:

|                |  |
|----------------|--|
| $T_A$          | = Ambient Temperature, °C                                      |
| $\theta_{JMA}$ | = Package Thermal Resistance, Junction-to-Ambient, °C/W        |
| $P_D$          | = $P_{INT} + P_{I/O}$  |
| $P_{INT}$      | = $I_{DD} \times IV_{DD}$ , Watts - Chip Internal Power        |
| $P_{I/O}$      | = Power Dissipation on Input and Output Pins - User Determined |

For most applications  $P_{I/O} < P_{INT}$  and can be ignored. An approximate relationship between  $P_D$  and  $T_j$  (if  $P_{I/O}$  is neglected) is:

$$P_D = \frac{K}{(T_j + 273^\circ\text{C})} \quad \text{Eqn. 2}$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273^\circ\text{C}) + \theta_{JMA} \times P_D^2 \quad \text{Eqn. 3}$$

where K is a constant pertaining to the particular part. K can be determined from Equation 3 by measuring  $P_D$  (at equilibrium) for a known  $T_A$ . Using this value of K, the values of  $P_D$  and  $T_j$  can be obtained by solving Equation 1 and Equation 2 iteratively for any value of  $T_A$ .





Table 7. DC Electrical Specifications (continued)

| Characteristic  | Symbol     | Min  | Max  | Unit    |
|---|------------|------|------|---------|
| SDRAM and FlexBus Output Low Voltage<br>Mobile DDR/Bus Input High Voltage (nominal 1.8V)<br>DDR/Bus Pad Supply Voltage (nominal 2.5V)<br>SDR/Bus Pad Supply Voltage (nominal 3.3V)<br>$I_{OL} = 5.0$ mA for all modes | $SDV_{OL}$ | —    | 0.3  | V       |
| Input Leakage Current<br>$V_{in} = V_{DD}$ or $V_{SS}$ , Input-only pins  | $I_{in}$   | -1.0 | 1.0  | $\mu$ A |
| Weak Internal Pull-Up Device Current, tested at $V_{IL}$ Max. <sup>1</sup>  | $I_{APU}$  | -10  | -130 | $\mu$ A |
| Input Capacitance <sup>2</sup><br>All input-only pins<br>All input/output (three-state) pins  | $C_{in}$   | —    | 7    | pF      |

<sup>1</sup> Refer to the signals section for pins having weak internal pull-up devices.

<sup>2</sup> This parameter is characterized before qualification rather than 100% tested.

## 5.5 Oscillator and PLL Electrical Characteristics

Table 8. PLL Electrical Characteristics

| Num | Characteristic  | Symbol             | Min. Value           | Max. Value   | Unit  |
|-----|---|--------------------|----------------------|--|-------|
| 1   | PLL Reference Frequency Range<br>Crystal reference<br>External reference                  | $f_{ref\_crystal}$ | 12                   | 25 <sup>1</sup>                                      | MHz   |
|     |   | $f_{ref\_ext}$     | 12                   | 40 <sup>1</sup>                                      | MHz   |
| 2   | Core frequency<br>CLKOUT Frequency <sup>2</sup>   | $f_{sys}$          | $488 \times 10^{-6}$ | 240  | MHz   |
|     |   | $f_{sys/3}$        | $163 \times 10^{-6}$ | 80   | MHz   |
| 3   | Crystal Start-up Time <sup>3, 4</sup>   | $t_{cst}$          | —                    | 10   | ms    |
| 4   | EXTAL Input High Voltage<br>Crystal Mode <sup>5</sup><br>All other modes (External, Limp) | $V_{IHEXT}$        | $V_{XTAL} + 0.4$     | —  | V     |
|     |   | $V_{IHEXT}$        | $E_{VDD}/2 + 0.4$    | —  | V     |
| 5   | EXTAL Input Low Voltage<br>Crystal Mode <sup>5</sup><br>All other modes (External, Limp)  | $V_{ILEXT}$        | —                    | $V_{XTAL} - 0.4$                                     | V     |
|     |   | $V_{ILEXT}$        | —                    | $E_{VDD}/2 - 0.4$                                    | V     |
| 7   | PLL Lock Time <sup>3, 6</sup>   | $t_{pll}$          | —                    | 50000  | CLKIN |
| 8   | Duty Cycle of reference <sup>3</sup>  | $t_{dc}$           | 40                   | 60   | %     |
| 9   | XTAL Current  | $I_{XTAL}$         | 1                    | 3  | mA    |
| 10  | Total on-chip stray capacitance on XTAL   | $C_{S\_XTAL}$      |                      | 1.5  | pF    |
| 11  | Total on-chip stray capacitance on EXTAL  | $C_{S\_EXTAL}$     |                      | 1.5  | pF    |
| 12  | Crystal capacitive load   | $C_L$              |                      | See crystal spec                                     |       |
| 13  | Discrete load capacitance for XTAL  | $C_{L\_XTAL}$      |                      | $2 * C_L - C_{S\_XTAL} - C_{PCB\_XTAL}$ <sup>7</sup> | pF    |

Table 8. PLL Electrical Characteristics (continued)

| Num | Characteristic   | Symbol         | Min. Value | Max. Value  | Unit                           |
|-----|--|----------------|------------|---|--------------------------------|
| 14  | Discrete load capacitance for EXTAL  | $C_{L\_EXTAL}$ |            | $2 * C_{L\_EXTAL} + C_{S\_EXTAL} + C_{PCB\_EXTAL}$ <sup>7</sup> | pF                             |
| 17  | CLKOUT Period Jitter, <sup>3, 4, 7, 8, 9</sup> Measured at $f_{SYS}$ Max<br>Peak-to-peak Jitter (Clock edge to clock edge)<br>Long Term Jitter | $C_{jitter}$   | —<br>—     | 10<br>TBD   | % $f_{sys/3}$<br>% $f_{sys/3}$ |
| 18  | Frequency Modulation Range Limit <sup>3, 10, 11</sup><br>( $f_{sys}$ Max must not be exceeded)   | $C_{mod}$      | 0.8        | 2.2   | % $f_{sys/3}$                  |
| 19  | VCO Frequency. $f_{VCO} = (f_{ref} * PFD)/4$   | $f_{VCO}$      | 350        | 540   | MHz                            |

<sup>1</sup> The maximum allowable input clock frequency when booting with the PLL enabled is 24MHz. For higher input clock frequencies the processor must boot in LIMP mode to avoid violating the maximum allowable CPU frequency.

<sup>2</sup> All internal registers retain data at 0 Hz.

<sup>3</sup> This parameter is guaranteed by characterization before qualification rather than 100% tested.

<sup>4</sup> Proper PC board layout procedures must be followed to achieve specifications.

<sup>5</sup> This parameter is guaranteed by design rather than 100% tested.

<sup>6</sup> This specification is the PLL lock time only and does not include oscillator start-up time.

<sup>7</sup>  $C_{PCB\_EXTAL}$  and  $C_{PCB\_XTAL}$  are the measured PCB stray capacitances on EXTAL and XTAL, respectively.

<sup>8</sup> Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum  $f_{sys}$ . Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the PLL circuitry via PLL  $V_{DD}$ ,  $EV_{DD}$ , and  $V_{SS}$  and variation in crystal oscillator frequency increase the  $C_{jitter}$  percentage for a given interval.

<sup>9</sup> Values are with frequency modulation disabled. If frequency modulation is enabled, jitter is the sum of  $C_{jitter} + C_{mod}$ .

<sup>10</sup> Modulation percentage applies over an interval of 10  $\mu$ s, or equivalently the modulation rate is 100 KHz.

<sup>11</sup> Modulation range determined by hardware design.

## 5.6 External Interface Timing Characteristics

Table 9 lists processor bus input timings.

### NOTE

All processor bus timings are synchronous; that is, input setup/hold and output delay with respect to the rising edge of a reference clock. The reference clock is the FB\_CLK output.

All other timing relationships can be derived from these values. Timings listed in Table 9 are shown in Figure 7 and Figure 8.

\* The timings are also valid for inputs sampled on the negative clock edge.

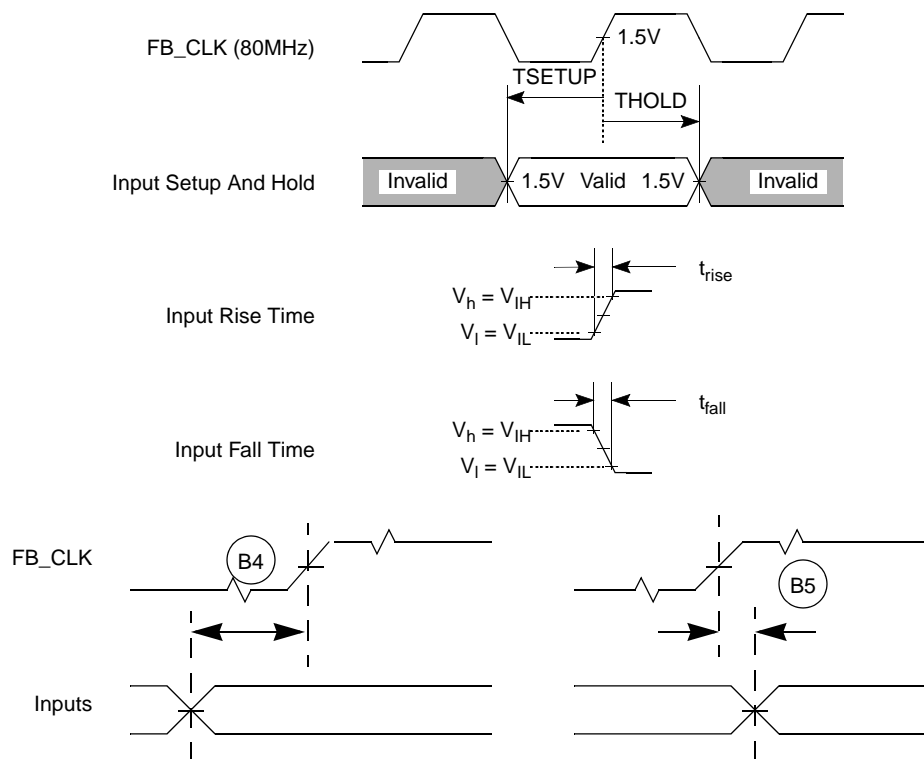


Figure 6. General Input Timing Requirements

## 5.6.1 FlexBus

A multi-function external bus interface called FlexBus is provided with basic functionality to interface to slave-only devices up to a maximum bus frequency of 80MHz. It can be directly connected to asynchronous or synchronous devices such as external boot ROMs, flash memories, gate-array logic, or other simple target (slave) devices with little or no additional circuitry. For asynchronous devices a simple chip-select based interface can be used. The FlexBus interface has six general purpose chip-selects ( $\overline{\text{FB\_CS}}[5:0]$ ) which can be configured to be distributed between the FlexBus or SDRAM memory interfaces. Chip-select,  $\overline{\text{FB\_CS0}}$  can be dedicated to boot ROM access and can be programmed to be byte (8 bits), word (16 bits), or longword (32 bits) wide. Control signal timing is compatible with common ROM/flash memories.

### 5.6.1.1 FlexBus AC Timing Characteristics

The following timing numbers indicate when data is latched or driven onto the external bus, relative to the system clock.

Table 9. FlexBus AC Timing Specifications

| Num | Characteristic   | Symbol                             | Min  | Max | Unit |
|-----|--|------------------------------------|------|-----|------|
| —   | Frequency of Operation   | $f_{\text{sys}/3}$                 | —    | 80  | Mhz  |
| FB1 | Clock Period (FB_CLK)  | $t_{\text{FBCK}} (t_{\text{cyc}})$ | 12.5 | —   | ns   |
| FB2 | Address, Data, and Control Output Valid ( $A[23:0]$ , $D[31:0]$ , $\overline{\text{FB\_CS}}[5:0]$ , $R/\overline{W}$ , $\overline{\text{TS}}$ , $\overline{\text{BE/BWE}}[3:0]$ and $\overline{\text{OE}}$ ) <sup>1</sup>    | $t_{\text{FBCHDCV}}$               | —    | 7.0 | ns   |
| FB3 | Address, Data, and Control Output Hold ( $A[23:0]$ , $D[31:0]$ , $\overline{\text{FB\_CS}}[5:0]$ , $R/\overline{W}$ , $\overline{\text{TS}}$ , $\overline{\text{BE/BWE}}[3:0]$ , and $\overline{\text{OE}}$ ) <sup>1,2</sup> | $t_{\text{FBCHDCI}}$               | 1    | —   | ns   |

Table 9. FlexBus AC Timing Specifications (continued)

| Num | Characteristic                                       | Symbol       | Min | Max | Unit |
|-----|--|--------------|-----|-----|------|
| FB4 | Data Input Setup                                     | $t_{DVFBCH}$ | 3.5 | —   | ns   |
| FB5 | Data Input Hold                                      | $t_{DIFBCH}$ | 0   | —   | ns   |
| FB6 | Transfer Acknowledge ( $\overline{TA}$ ) Input Setup | $t_{CVFBCH}$ | 4   | —   | ns   |
| FB7 | Transfer Acknowledge ( $\overline{TA}$ ) Input Hold  | $t_{CIFBCH}$ | 0   | —   | ns   |

- Timing for chip selects only applies to the  $\overline{FB\_CS}[5:0]$  signals. Please see Section 5.7.2, “DDR SDRAM AC Timing Characteristics” for  $\overline{SD\_CS}[3:0]$  timing.
- The FlexBus supports programming an extension of the address hold. Please consult the Reference Manual for more information.

**NOTE**

The processor drives the data lines during the first clock cycle of the transfer with the full 32-bit address. This may be ignored by standard connected devices using non-multiplexed address and data buses. However, some applications may find this feature beneficial.

The address and data busses are muxed between the FlexBus and SDRAM controller. At the end of the read and write bus cycles the address signals are indeterminate.

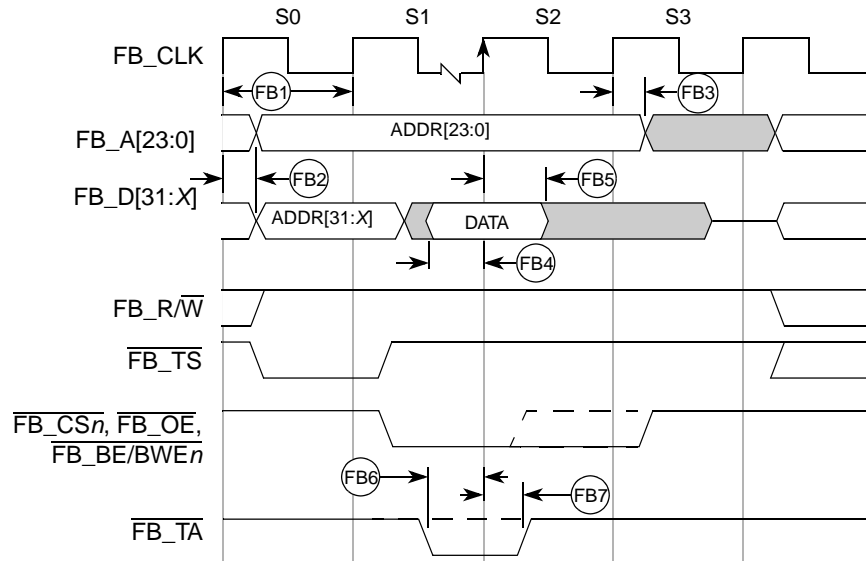


Figure 7. FlexBus Read Timing

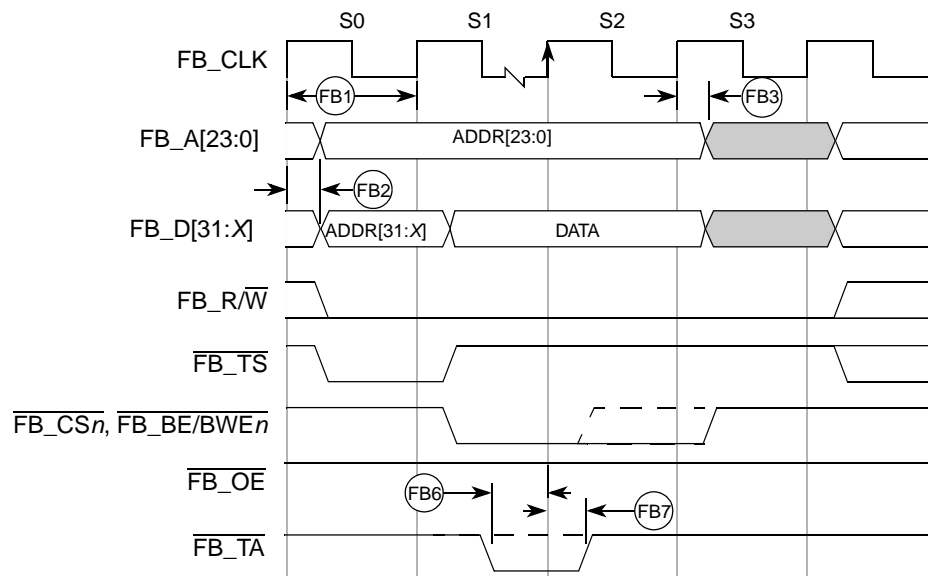


Figure 8. FlexBus Write Timing

## 5.7 SDRAM Bus

The SDRAM controller supports accesses to main SDRAM memory from any internal master. It supports standard SDRAM or double data rate (DDR) SDRAM, but it does not support both at the same time.

### 5.7.1 SDR SDRAM AC Timing Characteristics

The following timing numbers indicate when data is latched or driven onto the external bus, relative to the memory bus clock, when operating in SDR mode on write cycles and relative to SD\_DQS on read cycles. The device's SDRAM controller is a DDR controller that has an SDR mode. Because it is designed to support DDR, a DQS pulse must remain supplied to the device for each data beat of an SDR read. The processor accomplishes this by asserting a signal named SD\_SDR\_DQS during read cycles. Care must be taken during board design to adhere to the following guidelines and specs with regard to the SD\_SDR\_DQS signal and its usage.

Table 10. SDR Timing Specifications

| Symbol | Characteristic  | Symbol        | Min                   | Max                        | Unit   |
|--------|---|---------------|-----------------------|----------------------------|--------|
| •      | Frequency of Operation <sup>1</sup>   | •             | 60                    | 80                         | MHz    |
| SD1    | Clock Period <sup>2</sup>   | $t_{SDCK}$    | 12.5                  | 16.67                      | ns     |
| SD3    | Pulse Width High <sup>3</sup>   | $t_{SDCKH}$   | 0.45                  | 0.55                       | SD_CLK |
| SD4    | Pulse Width Low <sup>4</sup>  | $t_{SDCKL}$   | 0.45                  | 0.55                       | SD_CLK |
| SD5    | Address, $\overline{SD\_CKE}$ , $\overline{SD\_CAS}$ , $\overline{SD\_RAS}$ , $\overline{SD\_WE}$ , $\overline{SD\_BA}$ , $\overline{SD\_CS}[1:0]$ - Output Valid | $t_{SDCHACV}$ | —                     | $0.5 \times SD\_CLK + 1.0$ | ns     |
| SD6    | Address, $\overline{SD\_CKE}$ , $\overline{SD\_CAS}$ , $\overline{SD\_RAS}$ , $\overline{SD\_WE}$ , $\overline{SD\_BA}$ , $\overline{SD\_CS}[1:0]$ - Output Hold  | $t_{SDCHACI}$ | 2.0                   | —                          | ns     |
| SD7    | SD_SDR_DQS Output Valid <sup>5</sup>  | $t_{DQSOV}$   | —                     | Self timed                 | ns     |
| SD8    | SD_DQS[3:0] input setup relative to SD_CLK <sup>6</sup>   | $t_{DQVSDCH}$ | $0.25 \times SD\_CLK$ | $0.40 \times SD\_CLK$      | ns     |



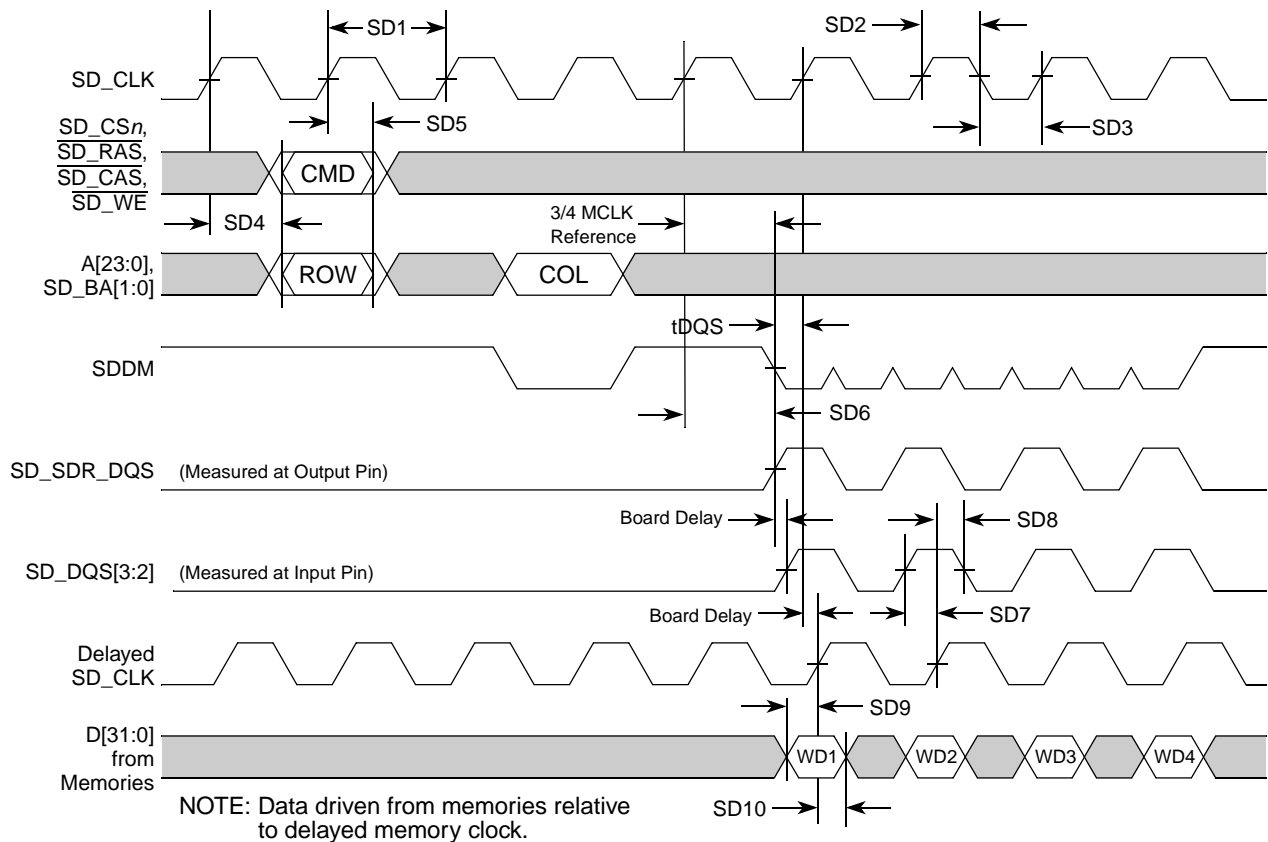


Figure 10. SDR Read Timing

### 5.7.2 DDR SDRAM AC Timing Characteristics

When using the SDRAM controller in DDR mode, the following timing numbers must be followed to properly latch or drive data onto the memory bus. All timing numbers are relative to the four DQS byte lanes.

Table 11. DDR Timing Specifications

| Num | Characteristic   | Symbol        | Min  | Max                        | Unit   |
|-----|--|---------------|------|----------------------------|--------|
| •   | Frequency of Operation   | $t_{DDCK}$    | 60   | 80                         | Mhz    |
| DD1 | Clock Period <sup>1</sup>  | $t_{DDSK}$    | 12.5 | 16.67                      | ns     |
| DD2 | Pulse Width High <sup>2</sup>  | $t_{DDCKH}$   | 0.45 | 0.55                       | SD_CLK |
| DD3 | Pulse Width Low <sup>3</sup>   | $t_{DDCKL}$   | 0.45 | 0.55                       | SD_CLK |
| DD4 | Address, $\overline{SD\_CKE}$ , $\overline{SD\_CAS}$ , $\overline{SD\_RAS}$ , $\overline{SD\_WE}$ , $\overline{SD\_CS}[1:0]$ - Output Valid <sup>3</sup> | $t_{SDCHACV}$ | —    | $0.5 \times SD\_CLK + 1.0$ | ns     |
| DD5 | Address, $\overline{SD\_CKE}$ , $\overline{SD\_CAS}$ , $\overline{SD\_RAS}$ , $\overline{SD\_WE}$ , $\overline{SD\_CS}[1:0]$ - Output Hold               | $t_{SDCHACI}$ | 2.0  | —                          | ns     |
| DD6 | Write Command to first DQS Latching Transition   | $t_{CMDVDQ}$  | —    | 1.25                       | SD_CLK |
| DD7 | Data and Data Mask Output Setup (DQ-->DQS) Relative to DQS (DDR Write Mode) <sup>4, 5</sup>  | $t_{DQDMV}$   | 1.5  | —                          | ns     |

Table 11. DDR Timing Specifications (continued)

| Num  | Characteristic  | Symbol               | Min                      | Max | Unit   |
|------|---|----------------------|--------------------------|-----|--------|
| DD8  | Data and Data Mask Output Hold (DQS-->DQ) Relative to DQS (DDR Write Mode) <sup>6</sup> | t <sub>DQDMI</sub>   | 1.0                      | —   | ns     |
| DD9  | Input Data Skew Relative to DQS (Input Setup) <sup>7</sup>                              | t <sub>DVDQ</sub>    | —                        | 1   | ns     |
| DD10 | Input Data Hold Relative to DQS <sup>8</sup>  | t <sub>DIDQ</sub>    | 0.25 × SD_CLK<br>+ 0.5ns | —   | ns     |
| DD11 | DQS falling edge from SDCLK rising (output hold time)                                   | t <sub>DQLSDCH</sub> | 0.5                      | —   | ns     |
| DD12 | DQS input read preamble width   | t <sub>DQRPRE</sub>  | 0.9                      | 1.1 | SD_CLK |
| DD13 | DQS input read postamble width  | t <sub>DQRPST</sub>  | 0.4                      | 0.6 | SD_CLK |
| DD14 | DQS output write preamble width   | t <sub>DQWPRE</sub>  | 0.25                     |     | SD_CLK |
| DD15 | DQS output write postamble width  | t <sub>DQWPST</sub>  | 0.4                      | 0.6 | SD_CLK |

<sup>1</sup> SD\_CLK is one SDRAM clock in (ns).

<sup>2</sup> Pulse width high plus pulse width low cannot exceed min and max clock period.

<sup>3</sup> Command output valid should be 1/2 the memory bus clock (SD\_CLK) plus some minor adjustments for process, temperature, and voltage variations.

<sup>4</sup> This specification relates to the required input setup time of today's DDR memories. The processor's output setup should be larger than the input setup of the DDR memories. If it is not larger, the input setup on the memory is in violation. MEM\_DATA[31:24] is relative to MEM\_DQS[3], MEM\_DATA[23:16] is relative to MEM\_DQS[2], MEM\_DATA[15:8] is relative to MEM\_DQS[1], and MEM\_[7:0] is relative MEM\_DQS[0].

<sup>5</sup> The first data beat is valid before the first rising edge of DQS and after the DQS write preamble. The remaining data beats are valid for each subsequent DQS edge.

<sup>6</sup> This specification relates to the required hold time of today's DDR memories. MEM\_DATA[31:24] is relative to MEM\_DQS[3], MEM\_DATA[23:16] is relative to MEM\_DQS[2], MEM\_DATA[15:8] is relative to MEM\_DQS[1], and MEM\_[7:0] is relative MEM\_DQS[0].

<sup>7</sup> Data input skew is derived from each DQS clock edge. It begins with a DQS transition and ends when the last data line becomes valid. This input skew must include DDR memory output skew and system level board skew (due to routing or other factors).

<sup>8</sup> Data input hold is derived from each DQS clock edge. It begins with a DQS transition and ends when the first data line becomes invalid.





## Electrical Characteristics

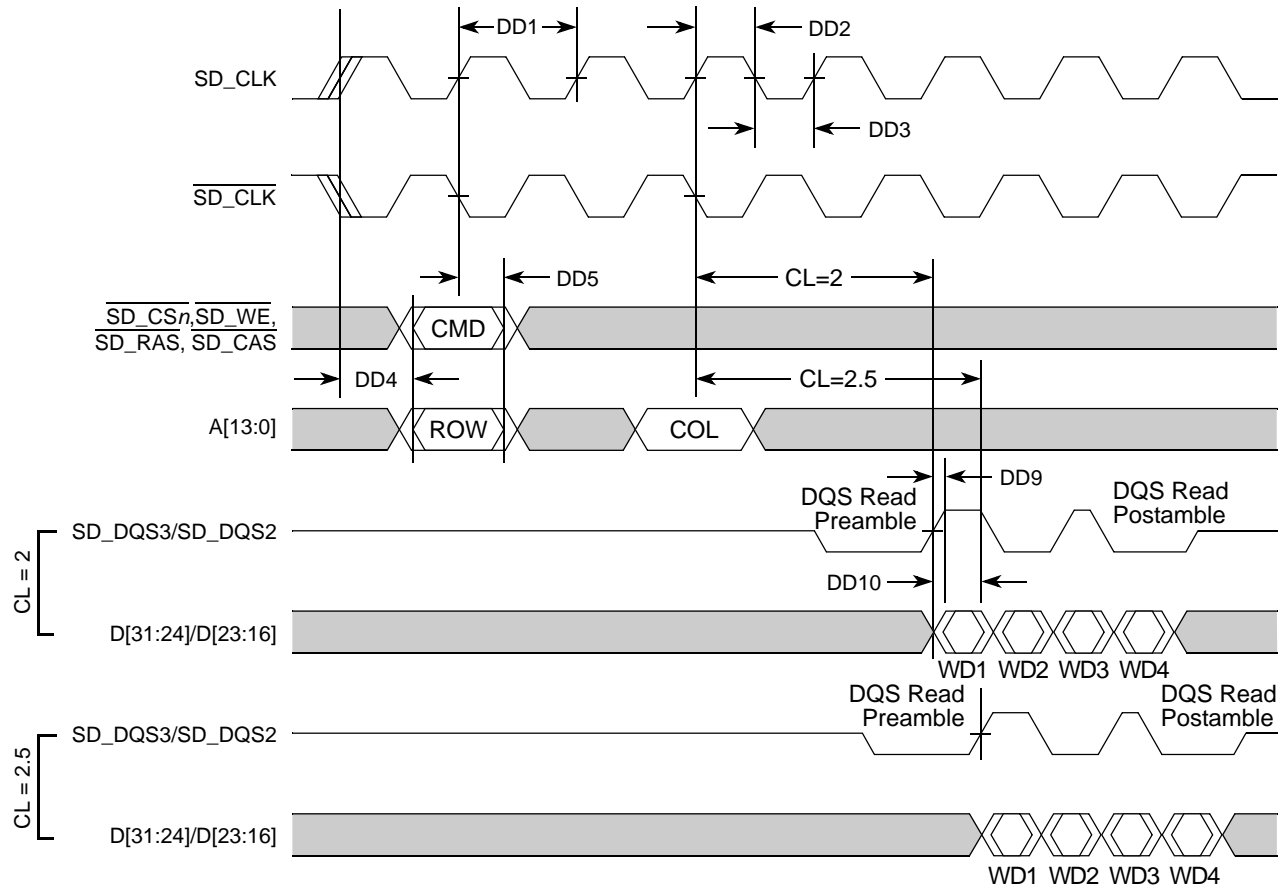


Figure 12. DDR Read Timing

## 5.8 General Purpose I/O Timing

Table 12. GPIO Timing<sup>1</sup>

| Num | Characteristic                     | Symbol      | Min | Max | Unit |
|-----|------------------------------------|-------------|-----|-----|------|
| G1  | FB_CLK High to GPIO Output Valid   | $t_{CHPOV}$ | —   | 10  | ns   |
| G2  | FB_CLK High to GPIO Output Invalid | $t_{CHPOI}$ | 1.5 | —   | ns   |
| G3  | GPIO Input Valid to FB_CLK High    | $t_{PVCH}$  | 9   | —   | ns   |
| G4  | FB_CLK High to GPIO Input Invalid  | $t_{CHPI}$  | 1.5 | —   | ns   |

<sup>1</sup> GPIO pins include:  $\overline{IRQ}_n$ , PWM, UART, FlexCAN, and Timer pins.

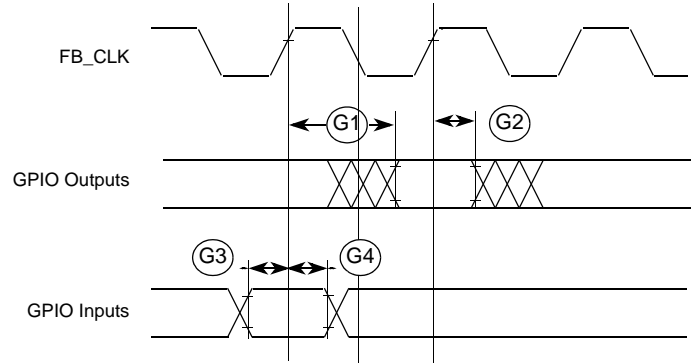


Figure 13. GPIO Timing

## 5.9 Reset and Configuration Override Timing

Table 13. Reset and Configuration Override Timing

| Num | Characteristic  | Symbol             | Min | Max | Unit             |
|-----|---|--------------------|-----|-----|------------------|
| R1  | $\overline{\text{RESET}}$ Input valid to FB_CLK High                        | $t_{\text{RVCH}}$  | 9   | —   | ns               |
| R2  | FB_CLK High to $\overline{\text{RESET}}$ Input invalid                      | $t_{\text{CHRI}}$  | 1.5 | —   | ns               |
| R3  | $\overline{\text{RESET}}$ Input valid Time <sup>1</sup>                     | $t_{\text{RIVT}}$  | 5   | —   | $t_{\text{CYC}}$ |
| R4  | FB_CLK High to $\overline{\text{RSTOUT}}$ Valid                             | $t_{\text{CHROV}}$ | —   | 10  | ns               |
| R5  | $\overline{\text{RSTOUT}}$ valid to Config. Overrides valid                 | $t_{\text{ROVCV}}$ | 0   | —   | ns               |
| R6  | Configuration Override Setup Time to $\overline{\text{RSTOUT}}$ invalid     | $t_{\text{COS}}$   | 20  | —   | $t_{\text{CYC}}$ |
| R7  | Configuration Override Hold Time after $\overline{\text{RSTOUT}}$ invalid   | $t_{\text{COH}}$   | 0   | —   | ns               |
| R8  | $\overline{\text{RSTOUT}}$ invalid to Configuration Override High Impedance | $t_{\text{ROICZ}}$ | —   | 1   | $t_{\text{CYC}}$ |

<sup>1</sup> During low power STOP, the synchronizers for the  $\overline{\text{RESET}}$  input are bypassed and  $\overline{\text{RESET}}$  is asserted asynchronously to the system. Thus,  $\overline{\text{RESET}}$  must be held a minimum of 100 ns.

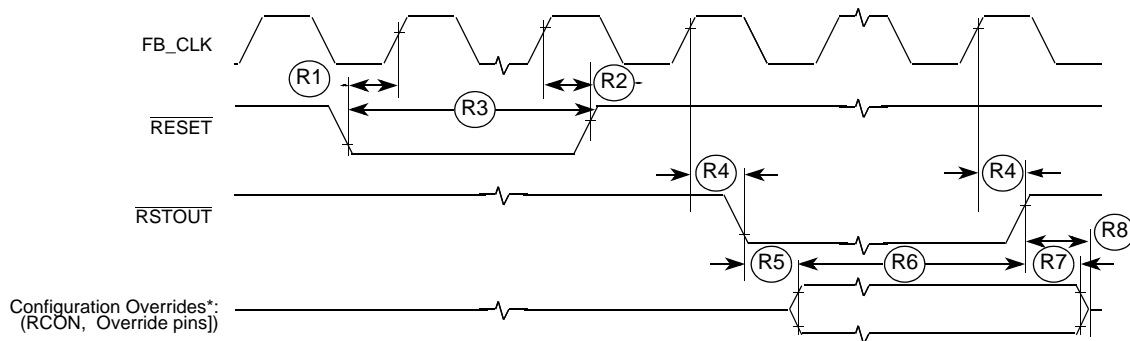


Figure 14.  $\overline{\text{RESET}}$  and Configuration Override Timing

### NOTE

Refer to the CCM chapter of the *MCF5373 Reference Manual* for more information.

Because of an order from the United States International Trade Commission, BGA-packaged product lines and part numbers indicated here currently are not available from Freescale for import or sale in the United States prior to September 2010: MCF53721CVM240, MCF53722CVM240, MCF53731CVM240, MCF53732CVM240, MCF53733CVM240

## 5.10 USB On-The-Go

The MCF5373 device is compliant with industry standard USB 2.0 specification.

## 5.11 SSI Timing Specifications

This section provides the AC timings for the SSI in master (clocks driven) and slave modes (clocks input). All timings are given for non-inverted serial clock polarity (SSI\_TCR[TSCKP] = 0, SSI\_RCR[RSCKP] = 0) and a non-inverted frame sync (SSI\_TCR[TFSI] = 0, SSI\_RCR[RFSI] = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timings remain valid by inverting the clock signal (SSI\_BCLK) and/or the frame sync (SSI\_FS) shown in the figures below.

**Table 14. SSI Timing – Master Modes<sup>1</sup>**

| Num | Description                                  | Symbol     | Min                | Max | Units      |
|-----|--|------------|--------------------|-----|------------|
| S1  | SSI_MCLK cycle time <sup>2</sup>             | $t_{MCLK}$ | $8 \times t_{SYS}$ | —   | ns         |
| S2  | SSI_MCLK pulse width high / low              |            | 45%                | 55% | $t_{MCLK}$ |
| S3  | SSI_BCLK cycle time <sup>3</sup>             | $t_{BCLK}$ | $8 \times t_{SYS}$ | —   | ns         |
| S4  | SSI_BCLK pulse width                         |            | 45%                | 55% | $t_{BCLK}$ |
| S5  | SSI_BCLK to SSI_FS output valid              |            | —                  | 15  | ns         |
| S6  | SSI_BCLK to SSI_FS output invalid            |            | -2                 | —   | ns         |
| S7  | SSI_BCLK to SSI_TXD valid                    |            | —                  | 15  | ns         |
| S8  | SSI_BCLK to SSI_TXD invalid / high impedance |            | -4                 | —   | ns         |
| S9  | SSI_RXD / SSI_FS input setup before SSI_BCLK |            | 15                 | —   | ns         |
| S10 | SSI_RXD / SSI_FS input hold after SSI_BCLK   |            | 0                  | —   | ns         |

<sup>1</sup> All timings specified with a capacitive load of 25pF.

<sup>2</sup> SSI\_MCLK can be generated from SSI\_CLKIN or a divided version of the internal system clock (SYSCLK).

<sup>3</sup> SSI\_BCLK can be derived from SSI\_CLKIN or a divided version of SYSCLK. If the SYSCLK is used, the minimum divider is 6. If the SSI\_CLKIN input is used, the programmable dividers must be set to ensure that SSI\_BCLK does not exceed  $4 \times t_{SYS}$ .

**Table 15. SSI Timing – Slave Modes<sup>1</sup>**

| Num | Description  | Symbol     | Min                | Max | Units      |
|-----|--|------------|--------------------|-----|------------|
| S11 | SSI_BCLK cycle time                                      | $t_{BCLK}$ | $8 \times t_{SYS}$ | —   | ns         |
| S12 | SSI_BCLK pulse width high/low                            |            | 45%                | 55% | $t_{BCLK}$ |
| S13 | SSI_FS input setup before SSI_BCLK                       |            | 10                 | —   | ns         |
| S14 | SSI_FS input hold after SSI_BCLK                         |            | 3                  | —   | ns         |
| S15 | SSI_BCLK to SSI_TXD/SSI_FS output valid                  |            | —                  | 15  | ns         |
| S16 | SSI_BCLK to SSI_TXD/SSI_FS output invalid/high impedance |            | -2                 | —   | ns         |
| S17 | SSI_RXD setup before SSI_BCLK                            |            | 10                 | —   | ns         |
| S18 | SSI_RXD hold after SSI_BCLK                              |            | 3                  | —   | ns         |

<sup>1</sup> All timings specified with a capacitive load of 25pF.













## Electrical Characteristics

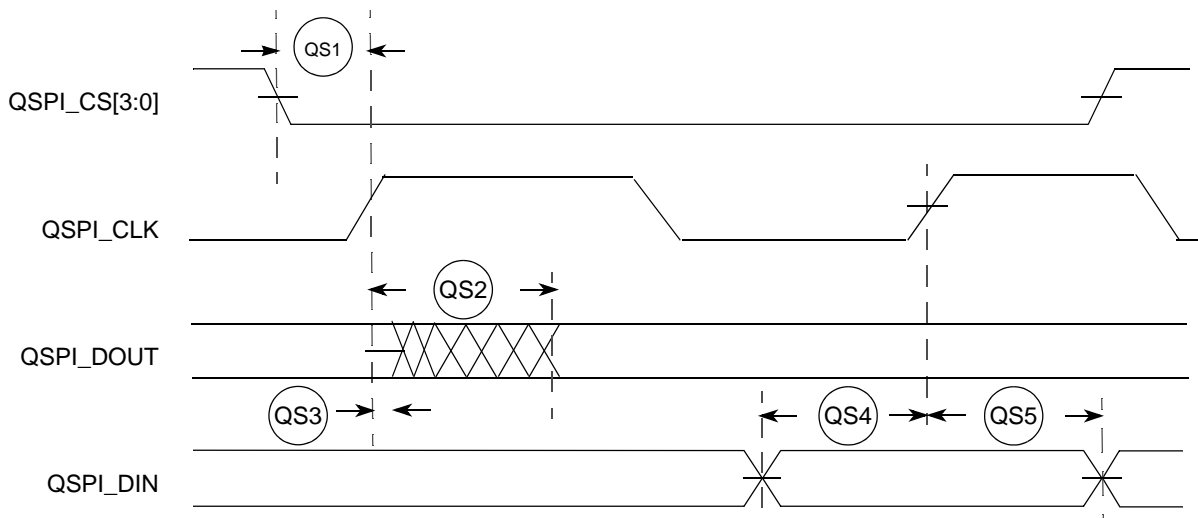


Figure 22. QSPI Timing

## 5.16 JTAG and Boundary Scan Timing

Table 24. JTAG and Boundary Scan Timing

| Num | Characteristics <sup>1</sup>                         | Symbol       | Min | Max | Unit        |
|-----|--|--------------|-----|-----|-------------|
| J1  | TCLK Frequency of Operation                          | $f_{JCYC}$   | DC  | 1/4 | $f_{sys}/3$ |
| J2  | TCLK Cycle Period                                    | $t_{JCYC}$   | 4   | —   | $t_{CYC}$   |
| J3  | TCLK Clock Pulse Width                               | $t_{JCW}$    | 26  | —   | ns          |
| J4  | TCLK Rise and Fall Times                             | $t_{JCRF}$   | 0   | 3   | ns          |
| J5  | Boundary Scan Input Data Setup Time to TCLK Rise     | $t_{BSDST}$  | 4   | —   | ns          |
| J6  | Boundary Scan Input Data Hold Time after TCLK Rise   | $t_{BSDHT}$  | 26  | —   | ns          |
| J7  | TCLK Low to Boundary Scan Output Data Valid          | $t_{BSDV}$   | 0   | 33  | ns          |
| J8  | TCLK Low to Boundary Scan Output High Z              | $t_{BSDZ}$   | 0   | 33  | ns          |
| J9  | TMS, TDI Input Data Setup Time to TCLK Rise          | $t_{TAPBST}$ | 4   | —   | ns          |
| J10 | TMS, TDI Input Data Hold Time after TCLK Rise        | $t_{TAPBHT}$ | 10  | —   | ns          |
| J11 | TCLK Low to TDO Data Valid                           | $t_{TDODV}$  | 0   | 26  | ns          |
| J12 | TCLK Low to TDO High Z                               | $t_{TDODZ}$  | 0   | 8   | ns          |
| J13 | $\overline{TRST}$ Assert Time                        | $t_{TRSTAT}$ | 100 | —   | ns          |
| J14 | $\overline{TRST}$ Setup Time (Negation) to TCLK High | $t_{TRSTST}$ | 10  | —   | ns          |

<sup>1</sup> JTAG\_EN is expected to be a static signal. Hence, specific timing is not associated with it.

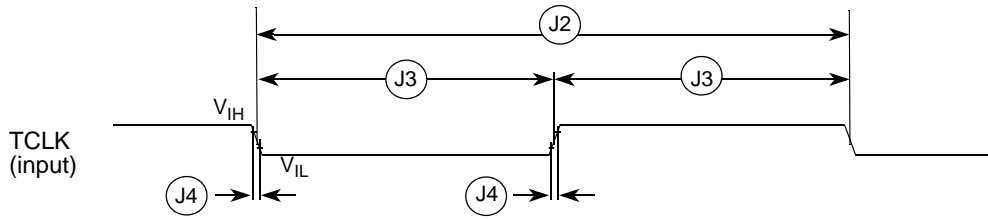


Figure 23. Test Clock Input Timing

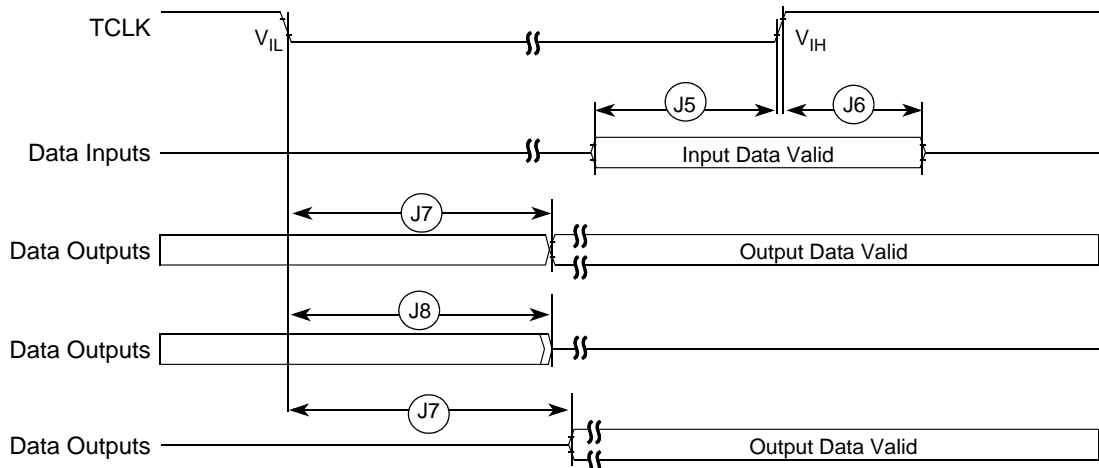


Figure 24. Boundary Scan (JTAG) Timing

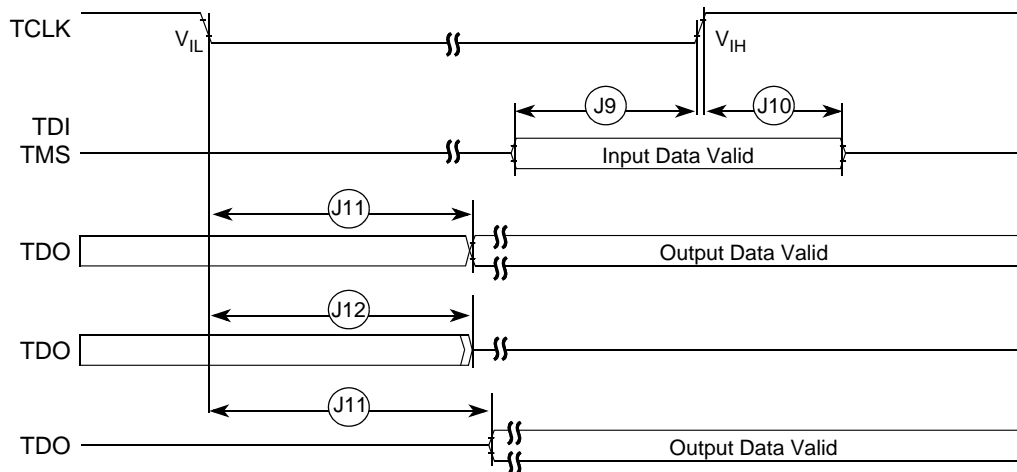


Figure 25. Test Access Port Timing

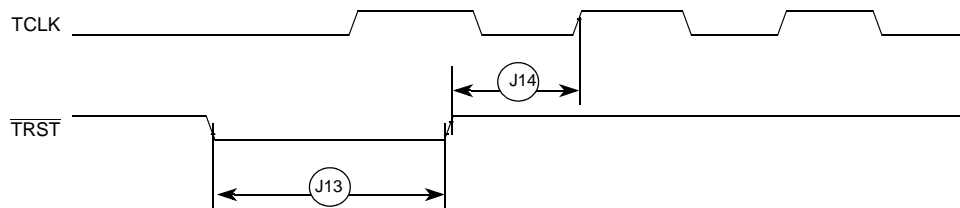


Figure 26. TRST Timing

## 5.17 Debug AC Timing Specifications

Table 25 lists specifications for the debug AC timing parameters shown in Figure 27.

Table 25. Debug AC Timing Specification

| Num             | Characteristic                    | Min | Max | Units                 |
|-----------------|-----------------------------------|-----|-----|-----------------------|
| D0              | PSTCLK cycle time                 | 2   | 2   | $t_{SYS} = 1/f_{SYS}$ |
| D1              | PSTCLK rising to PSTDDATA valid   | —   | 3.0 | ns                    |
| D2              | PSTCLK rising to PSTDDATA invalid | 1.5 | —   | ns                    |
| D3              | DSI-to-DSCLK setup                | 1   | —   | PSTCLK                |
| D4 <sup>1</sup> | DSCLK-to-DSO hold                 | 4   | —   | PSTCLK                |
| D5              | DSCLK cycle time                  | 5   | —   | PSTCLK                |
| D6              | BKPT assertion time               | 1   | —   | PSTCLK                |

<sup>1</sup> DSCLK and DSI are synchronized internally. D4 is measured from the synchronized DSCLK input relative to the rising edge of PSTCLK.

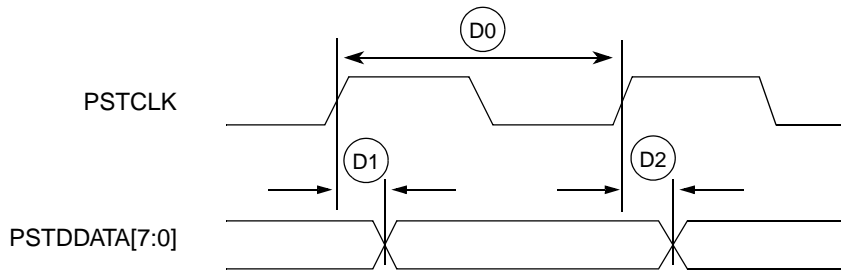


Figure 27. Real-Time Trace AC Timing

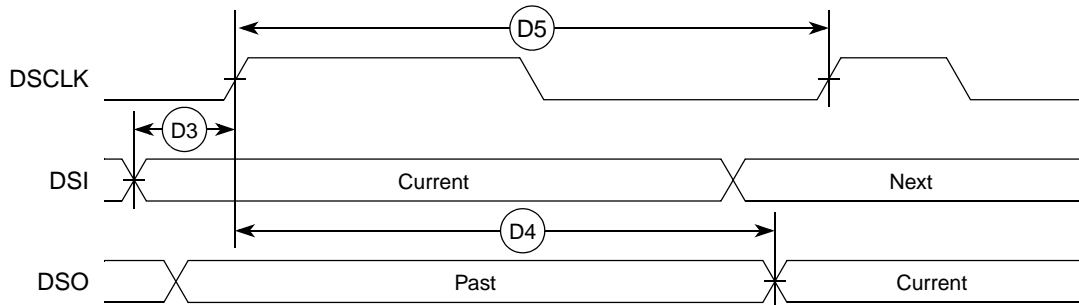


Figure 28. BDM Serial Port AC Timing

## 6 Current Consumption

All current consumption data is lab data measured on a single device using an evaluation board. Table 26 shows the typical power consumption in low-power modes. These current measurements are taken after executing a STOP instruction.

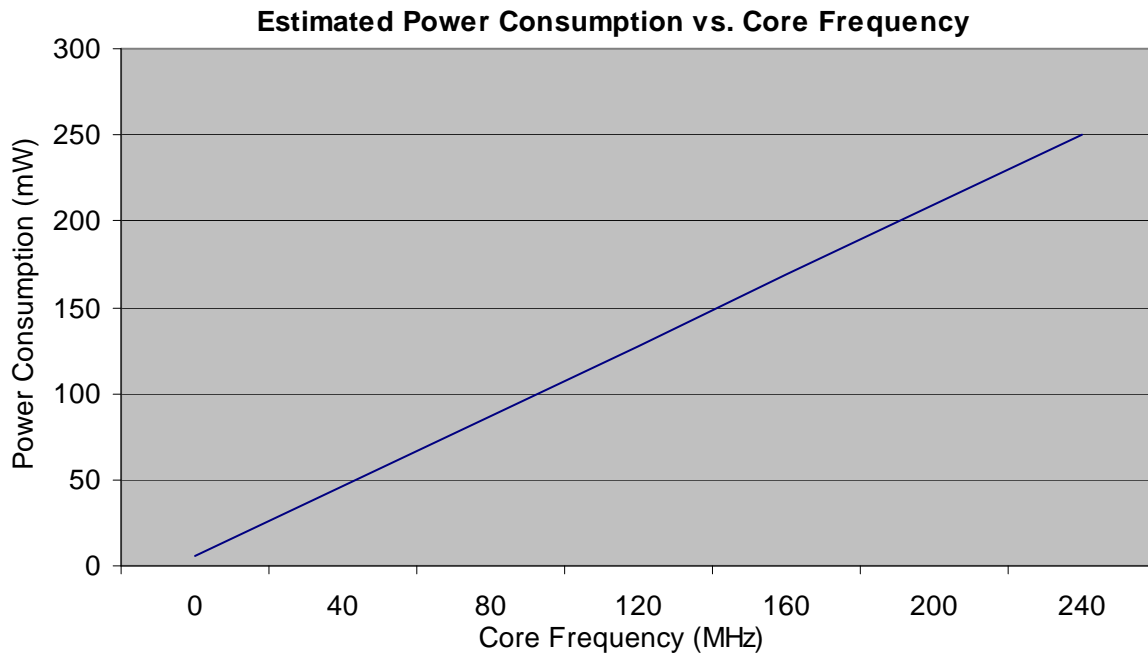


**Table 27. Typical Active Current Consumption Specifications<sup>1</sup>**

| $f_{sys/3}$ Frequency | Voltage | Typical <sup>2</sup> Active (Flash) | Peak <sup>3</sup> | Unit |
|-----------------------|---------|-------------------------------------|-------------------|------|
| 1.333 MHz             | 3.3V    | 7.73                                | 7.74              | mA   |
|                       | 1.5V    | 2.87                                | 3.56              |      |
| 2.666 MHz             | 3.3V    | 8.57                                | 8.60              |      |
|                       | 1.5V    | 4.37                                | 5.52              |      |
| 58 MHz                | 3.3V    | 40.10                               | 49.3              |      |
|                       | 1.5V    | 65.90                               | 91.70             |      |
| 64 MHz                | 3.3V    | 44.40                               | 54.0              |      |
|                       | 1.5V    | 69.50                               | 97.0              |      |
| 72 MHz                | 3.3V    | 53.6                                | 63.7              |      |
|                       | 1.5V    | 74.6                                | 104.7             |      |
| 80 MHz                | 3.3V    | 63.0                                | 73.7              |      |
|                       | 1.5V    | 79.6                                | 112.9             |      |

- <sup>1</sup> All values are measured with a 3.30 V EV<sub>DD</sub>, 3.30 V SDV<sub>DD</sub> and 1.5 V IV<sub>DD</sub> power supplies. Tests performed at room temperature with pins configured for high drive strength.
- <sup>2</sup> CPU polling a status register. All peripheral clocks except UART0, FlexBus, INTC0, reset controller, PLL, and edge port disabled.
- <sup>3</sup> Peak current measured while running a while(1) loop with all modules active.

Figure 30 shows the estimated maximum power consumption.



**Figure 30. Estimated Maximum Power Consumption**

## 7 Package Information

This section contains drawings showing the pinout and the packaging and mechanical characteristics of the MCF537x devices.

### NOTE

The mechanical drawings are the latest revisions at the time of publication of this document. The most up-to-date mechanical drawings can be found at the product summary page located at <http://www.freescale.com/coldfire>.

Because of an order from the United States International Trade Commission, BGA-packaged product lines and part numbers indicated here currently are not available from Freescale for import or sale in the United States prior to September 2010: MCF53721CVM240, MCF53722CVM240, MCF53723CVM240

## 7.1 Package Dimensions—196 MAPBGA

Figure 31 shows the MCF5373LCVM240, MCF5372LCVM240, and MCF53721CVM240 package dimensions.

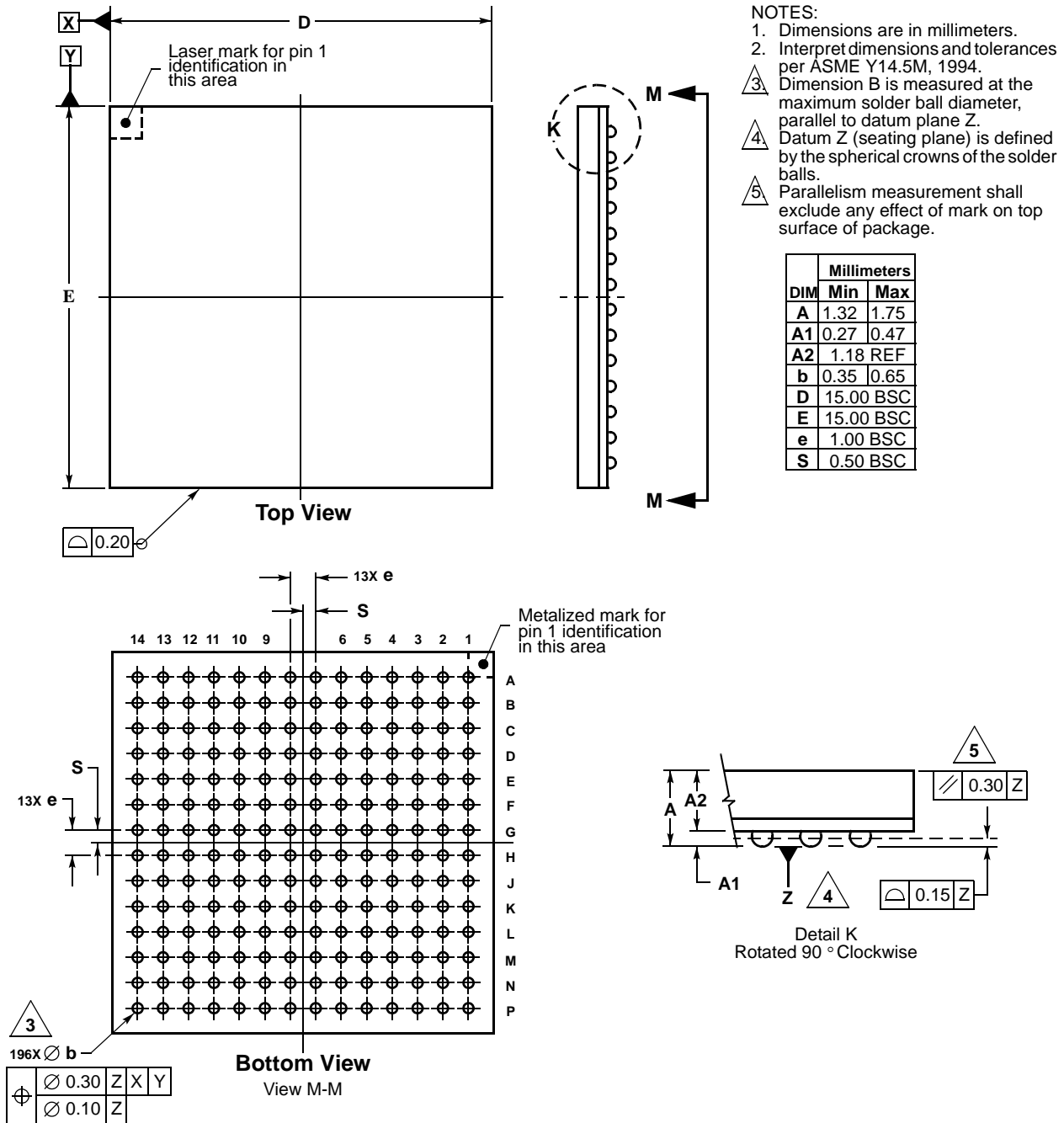


Figure 31. 196 MAPBGA Package Dimensions (Case No. 1128A-01)



## 7.2 Package Dimensions—160 QFP

Figure 32 and Figure 33 show the MCF5372CAB180 and MCF5373CAB180 package dimensions.

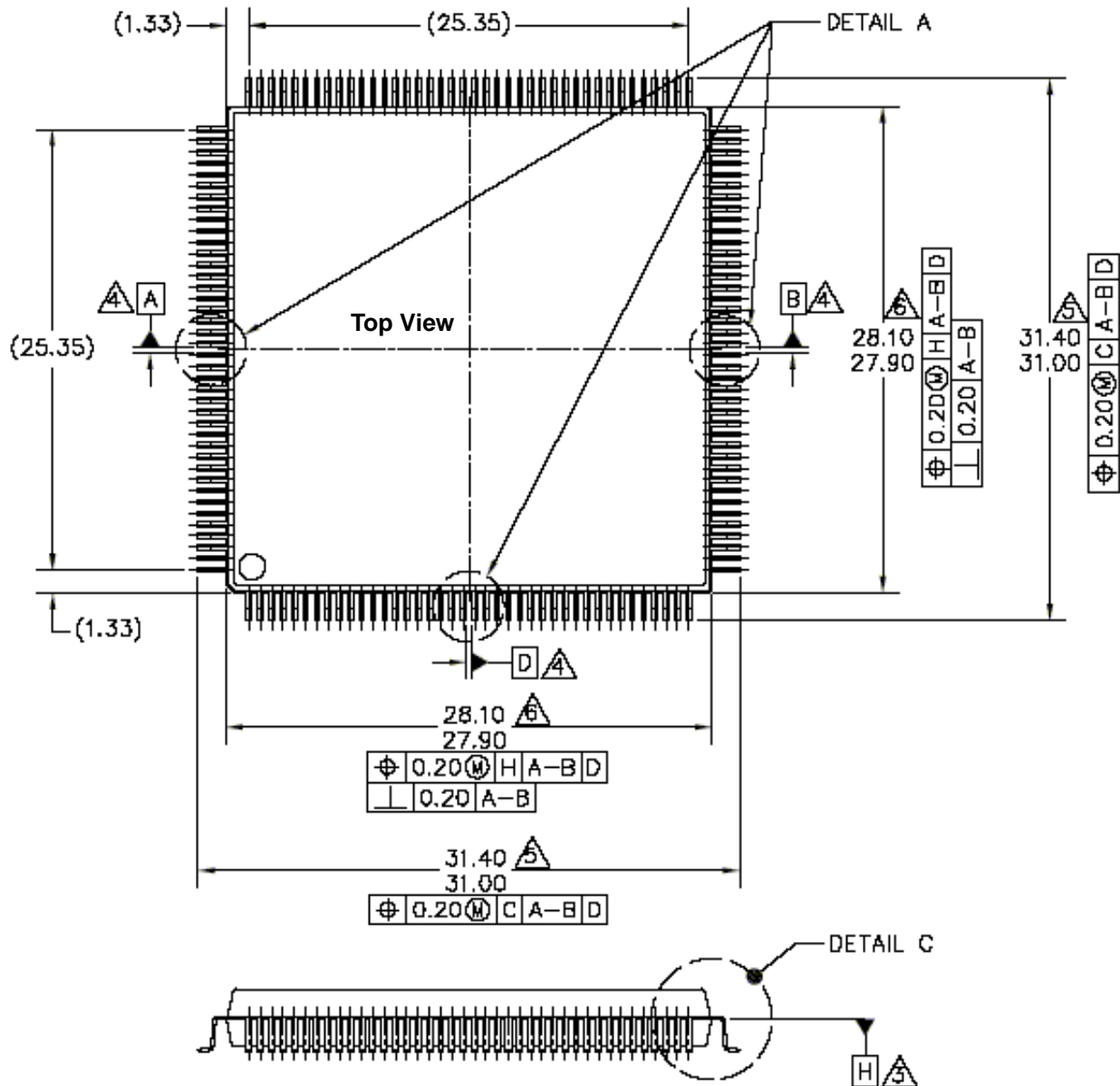
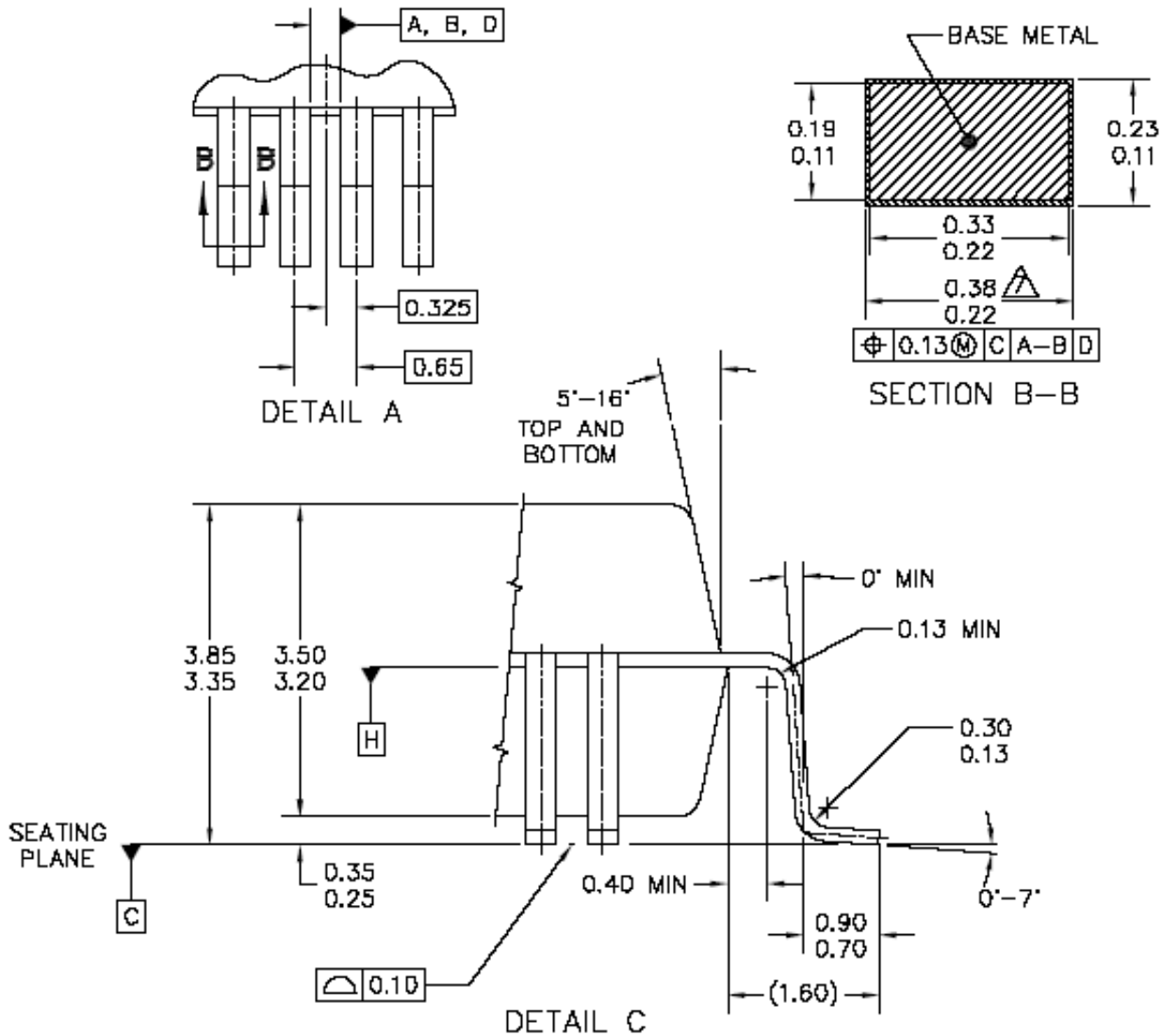


Figure 32. 160QFP Package Dimensions (Sheet 1 of 2)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

Figure 33. 160QFP Package Dimensions (Sheet 2 of 2)

## 8 Revision History

Table 28. MCF5373DS Document Revision History

| Rev. No. | Substantive Changes   | Date of Release |
|----------|---|-----------------|
| 0        | <ul style="list-style-type: none"> <li>Initial release</li> </ul>   | 11/2005         |
| 0.1      | <ul style="list-style-type: none"> <li>Swapped pin locations PLL_VSS (J11-&gt;H11) and DRAMSEL (H11-&gt;J11) in <a href="#">Table 1</a>. <a href="#">Figure 4</a> is correct.</li> </ul>  | 12/2005         |
| 0.2      | <ul style="list-style-type: none"> <li>Added not to <a href="#">Section 7, "Package Information."</a></li> <li>Added "top view" and "bottom view" where appropriate in mechanical drawings and pinout figures.</li> <li><a href="#">Figure 6</a>: Corrected "FB_CLK (75MHz)" label to "FB_CLK (80MHz)"</li> </ul>   | 3/2006          |
| 0.3      | <ul style="list-style-type: none"> <li>Changed 160QFP pinouts in <a href="#">Figure 5</a> and <a href="#">Table 2</a>: Removed IRQ3 pin, shifted pins 89–99 up one pin to 90–100. Pin 89 is now VSS.</li> <li><a href="#">Table 2</a>: Rearranged GPIO signal names for FEC pins.</li> <li>Removed ULPI specifications as the device does not support ULPI.</li> </ul>  | 4/2006          |
| 1        | <ul style="list-style-type: none"> <li>Updated thermal characteristic values in <a href="#">Table 7</a>.</li> <li>Updated DC electricals values in <a href="#">Table 7</a>.</li> <li>Updated <a href="#">Section 3.3, "Supply Voltage Sequencing and Separation Cautions"</a> and subsections.</li> <li>Updated and added Oscillator/PLL characteristics in <a href="#">Table 8</a>.</li> <li><a href="#">Table 9</a>: Swapped min/max for FB1; Removed FB8 &amp; FB9.</li> <li>Updated SDRAM write timing diagram, <a href="#">Figure 9</a>.</li> <li><a href="#">Table 11</a>: Added values for frequency of operation and DD1.</li> <li>Replaced figure &amp; table <a href="#">Section 5.11, "SSI Timing Specifications,"</a> with slave &amp; master mode versions.</li> <li>Removed second sentence from <a href="#">Section 5.13.2, "MII Transmit Signal Timing,"</a> regarding no minimum frequency requirement for TXCLK.</li> <li>Removed third and fourth paragraphs from <a href="#">Section 5.13.2, "MII Transmit Signal Timing,"</a> as this feature is not supported on this device.</li> <li>Updated figure &amp; table <a href="#">Section 5.17, "Debug AC Timing Specifications."</a></li> <li>Renamed &amp; moved previous version's <a href="#">Section 5.5 "Power Consumption"</a> to <a href="#">Section 6, "Current Consumption."</a> Added additional real-world data to this section as well.</li> </ul> | 7/2007          |
| 2        | <ul style="list-style-type: none"> <li>Added MCF53721 device information throughout: features list, family configuration table, ordering information table, signals description table, and relevant package diagram titles</li> <li>Remove Footnote 1 from <a href="#">Table 11</a>.</li> <li>Changed document type from Advance Information to Technical Data.</li> </ul>  | 8/2007          |

**Table 28. MCF5373DS Document Revision History (continued)**

| Rev. No. | Substantive Changes   | Date of Release |
|----------|---|-----------------|
| 3        | <ul style="list-style-type: none"> <li>• Removed cryptography from <a href="#">Table 1</a> for the MCF53721 device.</li> <li>• Corrected D0 spec in <a href="#">Table 25</a> from <math>1.5 \times t_{sys}</math> to <math>2 \times t_{sys}</math> for min and max values.</li> <li>• Updated FlexBus read and write timing diagrams in <a href="#">Figure 7</a> and <a href="#">Figure 8</a>.</li> <li>• Corrected package information in <a href="#">Table 2</a> for MCF5373LCVM240 device from “256 MAPBGA” to “196 MAPBGA”.</li> <li>• Removed footnote 2 from the IRQ[7:1] alternate functions USBHOST VBUS_EN, USBHOST VBUS_OC, SSI_MCLK, USB_CLKIN, and SSI_CLKIN signals in <a href="#">Table 6</a>.</li> </ul> | 4/2008          |
| 4        | <p>Changed the following specs in <a href="#">Table 10</a> and <a href="#">Table 11</a>:</p> <ul style="list-style-type: none"> <li>• Minimum frequency of operation from TBD to 60MHz</li> <li>• Maximum clock period from TBD to 16.67 ns</li> </ul> <p>Added FlexCAN for the MCF53721 device in features list, block diagram, Signal Information and Muxing table, and GPIO timing diagram</p>   | 11/2008         |

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Rev. 4

11/2008

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